



Arria II GX FPGA Development Board, 6G Edition

Reference Manual



101 Innovation Drive
San Jose, CA 95134
www.altera.com

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This document describes the hardware features of the Arria® II GX FPGA development board, 6G Edition, including the detailed pin-out and component reference information required to create custom FPGA designs that interface with all components of the board.

General Description

The Arria II GX FPGA development board, 6G Edition provides a hardware platform for developing and prototyping low-power, high-performance, and logic-intensive designs. The board provides a wide range of peripherals and memory interfaces to facilitate the development of the Arria II GX FPGA designs.

Two high-speed mezzanine card (HSMC) connector is available to add additional functionality via a variety of HSMCs available from Altera® and various partners.



To see a list of the latest HSMCs available or to download a copy of the HSMC specification, refer to the [Development Board Daughtercards](#) page of the Altera website.

Design advancements and innovations, such as the 6.375-Gbps transceiver modules, the PCI Express hard IP implementation, and programmable power technology ensure that designs implemented in the Arria II GX FPGAs operate faster, with lower power, and have a faster time to market than previous FPGA families.



For more information on the following topics, refer to the respective documents:

- Arria II device family, refer to the [Arria II GX Device Handbook](#).
- PCI Express MegaCore function, refer to the [PCI Express Compiler User Guide](#).
- HSMC Specification, refer to the [High Speed Mezzanine Card \(HSMC\) Specification](#).

Board Component Blocks

The board features the following major component blocks:

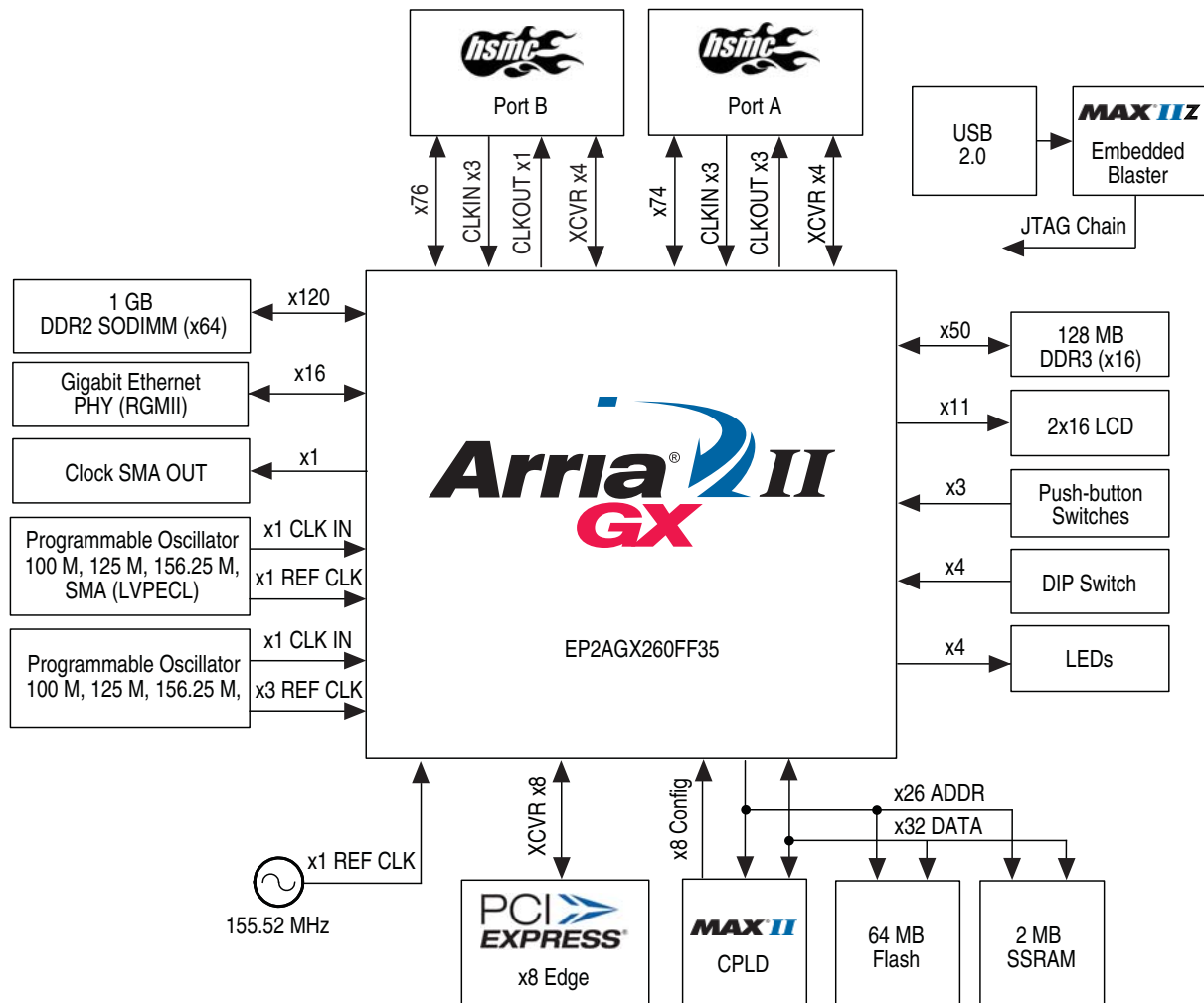
- Arria II GX EP2AGX260FF35 FPGA in the 1152-pin FineLine BGA (FBGA) package
 - 244,188 LEs
 - 102,600 adaptive logic modules (ALMs)
 - 11,756 Kbit on-die memory
 - 16 high-speed transceivers
 - 6 phase locked loops (PLLs)
 - 736 18x18 multipliers
 - 0.9-V core power
- MAX[®] II EPM2210F256 CPLD in the 256-pin FBGA package
 - 2.5-V core power
- FPGA configuration circuitry
 - MAX II CPLD EPM2210 System Controller and flash fast passive parallel (FPP) configuration
 - On-board USB-Blaster[™] for use with the Quartus[®] II Programmer
- On-Board ports
 - Two HSMC expansion port
 - One gigabit Ethernet port
- On-Board memory
 - 128-Mbyte 16-bit DDR3 memory
 - 1-Gbyte 64-bit DDR2 small outline DIMM (SODIMM)
 - 2-Mbyte Synchronous Static Random Access Memory (SSRAM)
 - 64-Mbyte flash memory
- On-Board clocking circuitry
 - Five on-board oscillator
 - 50-MHz oscillator
 - 100-MHz oscillator
 - 155.52-MHz oscillator
 - Programmable oscillator with a default frequency of 125-MHz
 - Programmable oscillator with a default frequency of 100-MHz
 - SMA connectors for external LVPECL clock input
 - SMA connector for clock output

- General user I/O
 - LEDs and displays
 - Four user LEDs
 - Two-line character LCD display
 - Three configuration select LED
 - One configuration done LED
 - Two HSMC interface transmit/receive LED (TX/RX)
 - Three PCI Express LEDs
 - Five Ethernet LEDs
 - Push-Button switches
 - One CPU reset push-button switch
 - One Max II CPLD EPM2210 System Controller configuration reset push-button switch
 - One load image push-button switch (to program the FPGA from flash memory)
 - One image select push-button switch (select image to load from flash memory)
 - Two general user push-button switches
 - DIP switches
 - Four user DIP switches
 - Eight MAX II control DIP switches
- Power supply
 - 14-V – 20-V DC input
 - PCI Express edge connector power
 - On-board power measurement circuitry
- Mechanical
 - PCI Express full-length standard-height (8.48" x 4.376")
 - PCI Express chassis or bench-top operation

Development Board Block Diagram

Figure 1-1 shows the block diagram of the Arria II GX FPGA development board, 6G Edition.

Figure 1-1. Arria II GX FPGA Development Board, 6G Edition Block Diagram



Handling the Board

When handling the board, it is important to observe the following static discharge precaution:



Without proper anti-static handling, the board can be damaged. Therefore, use anti-static handling precautions when touching the board.

Introduction

This chapter introduces the major components on the Arria II GX FPGA development board, 6G Edition. [Figure 2-1](#) illustrates major component locations and [Table 2-1](#) provides a brief description of all component features of the board.



A complete set of schematics, a physical layout database, and GERBER files for the development board reside in the Arria II GX development kit documents directory.



For information about powering up the board and installing the demonstration software, refer to the *Arria II GX FPGA Development Kit, 6G Edition User Guide*.

This chapter consists of the following sections:

- “Board Overview”
- “Featured Device: Arria II GX Device” on page 2-4
- “MAX II CPLD EPM2210 System Controller” on page 2-6
- “Configuration, Status, and Setup Elements” on page 2-11
- “Clock Circuitry” on page 2-20
- “General User Input/Output” on page 2-23
- “Components and Interfaces” on page 2-27
- “Memory” on page 2-38
- “Power Supply” on page 2-49
- “Statement of China-RoHS Compliance” on page 2-52

Board Overview

This section provides an overview of the Arria II GX FPGA development board, 6G Edition, including an annotated board image and component descriptions. [Figure 2-1](#) provides an overview of the development board features.

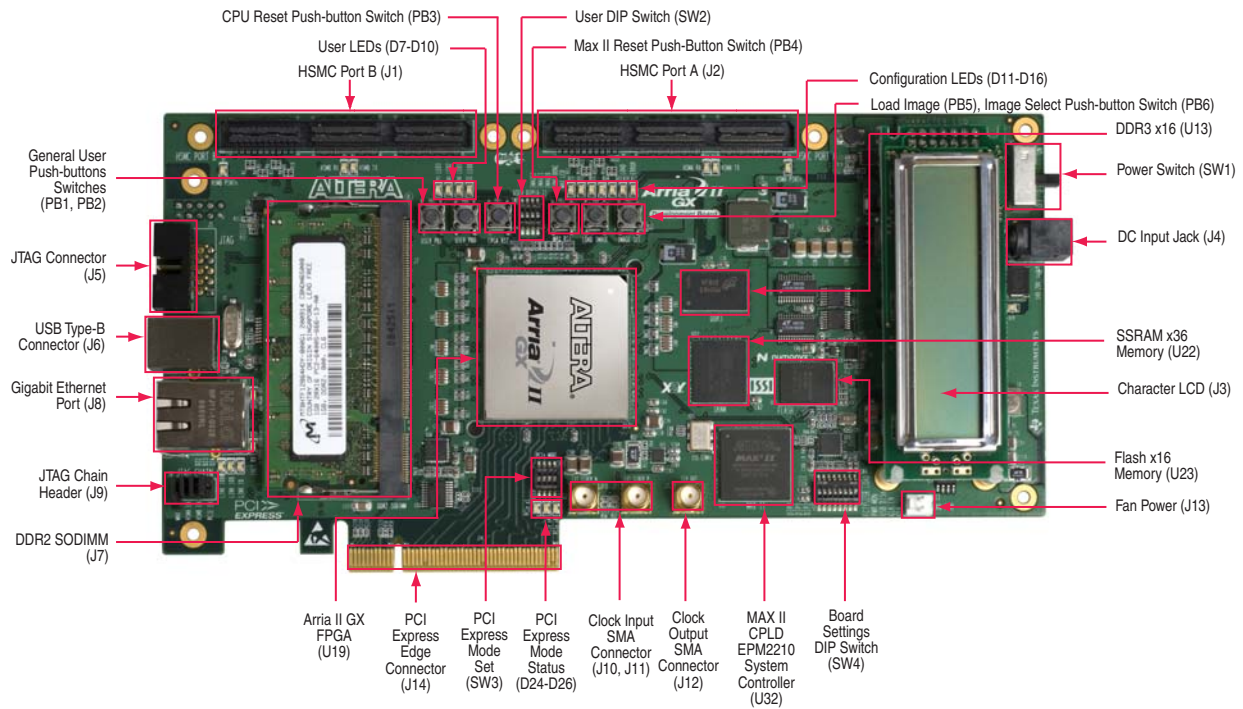
Figure 2–1. Overview of the Arria II GX FPGA Development Board, 6G Edition Features

Table 2–1 describes the components and lists their corresponding board references.

Table 2–1. Arria II GX FPGA Development Board, 6G Edition Components (Part 1 of 3)

Board Reference	Type	Description
Featured Devices		
U19	FPGA	EP2AGX260FF35, 1152-pin FBGA.
U32	CPLD	EPM2210F256, 256-pin FBGA.
Configuration, Status, and Setup Elements		
J6	USB type-B connector	Connects to the computer to enable embedded USB-Blaster JTAG.
J9	JTAG chain header	Enables and disables devices in the JTAG chain.
SW4	Board settings DIP switch	Controls the MAX II CPLD EPM2210 System Controller functions such as clock enable, SMA clock input control, and which image to load from flash memory at power-up.
J5	JTAG connector	Disables embedded blaster (for use with external USB-Blasters).
SW3	PCI Express DIP switch	Controls the PCI Express lane width by connecting <code>prstnt</code> pins together on the PCI Express edge connector.
D14	Configuration done LED	Illuminates when the FPGA is configured.
D15	Load LED	Illuminates when the MAX II CPLD EPM2210 System Controller is actively configuring the FPGA.
D16	Error LED	Illuminates when the FPGA configuration from flash memory fails.
D18	Power LED	Illuminates when 2.5-V power is present.

Table 2-1. Arria II GX FPGA Development Board, 6G Edition Components (Part 2 of 3)

Board Reference	Type	Description
D11, D12, D13	Configuration LEDs	Illuminates to show the LED sequence that determines which flash memory image loads to the FPGA when <code>LOAD_IMAGE</code> is pressed.
D19, D20, D21, D22, D23	Ethernet LEDs	Shows the connection speed as well as transmit or receive activity.
D4, D5	HSMC port A LEDs	You can configure these LEDs to indicate transmit or receive activity.
D6	HSMC port A present LED	Illuminates when a daughtercard is plugged into the HSMC port A.
D2, D3	HSMC port B LEDs	You can configure these LEDs to indicate transmit or receive activity (only populated when a EP2AGX260 device is installed).
D1	HSMC port B present LED	Illuminates when a daughtercard is plugged into the HSMC port B (only populated when a EP2AGX260 device is installed).
D24, D25, D26	PCI Express link LEDs	You can configure these LEDs to display the PCI Express link width (x1, x4, x8).
Clock Circuitry		
U26	Programmable oscillator (125 MHz default)	Programmable oscillator with a default frequency of 125.00 MHz. The frequency is programmable using the MAX II CPLD EPM2210 System Controller. For general use such as memories, gigabit Ethernet (125 M/156.25 M), Serial RapidIO™ (SRIO) (125 M), or PCI Express (100 M).
U30	Programmable oscillator (100 MHz default)	Programmable oscillator with a default frequency of 100.00 MHz. The frequency is programmable using the MAX II CPLD EPM2210 System Controller. For general use such as memories, gigabit Ethernet (125 M/156.25 M), SRIO (125 M), PCI Express (100 M), or XAUI (156.25 M). Multiplex with <code>CLKIN_SMA_P</code> based on <code>CLK_SEL</code> switch value.
Y5	50 MHz oscillator	50.000 MHz crystal oscillator for general purpose logic.
Y6	100 MHz oscillator	100.000 MHz crystal oscillator for general purpose logic.
U25	155.52 MHz oscillator	155.520 MHz crystal oscillator for SONET.
J10, J11	Clock input SMAs	Drive LVPECL-compatible clock inputs into the clock multiplexer buffer (U33).
J12	Clock output SMA	Drive out 2.5-V CMOS clock output from the FPGA.
General User Input/Output		
D7, D8, D9, D10	User LEDs	Four user LEDs. Illuminates when driven low.
SW2	User DIP switch	Quad user DIP switches. When the switch is ON, a logic 0 is selected.
PB3	CPU reset push-button switch	Press to reset the FPGA logic.
PB4	MAX II reset push-button switch	Press to reset the MAX II CPLD EPM2210 System Controller.
PB1, PB2	General user push-button switches	Two user push-button switches. Driven low when pressed.
PB6	Image select push-button switch	Toggles the configuration LEDs which selects the program image that loads from flash memory to the FPGA.
PB5	Load image push-button switch	Load image from flash memory to the FGPA based on the configuration LED setting.

Table 2-1. Arria II GX FPGA Development Board, 6G Edition Components (Part 3 of 3)

Board Reference	Type	Description
Memory Devices		
J7	DDR2 SODIMM	DDR2 x64 SODIMM 200-pin connector and is populated with a 1-Gbyte memory module.
U13	DDR3 x16 memory	Independent 16-bit 128-Mbyte DDR3 memory port.
U22	SSRAM x36 memory	Standard synchronous RAM which makes a 36-bit 2-Mbyte SRAM port.
U23	Flash x16 memory	Synchronous burst mode flash device which provides a 16-bit 64-Mbyte non-volatile memory port.
Communication Ports		
J14	PCI Express edge connector	Made of gold-plated edge fingers for up to ×8 signaling in Gen1 mode.
J2	HSMC port A	Provides four transceiver channels and 80 CMOS or 17 LVDS channels per the HSMC specification.
J1	HSMC port B	Provides four transceiver channels and 78 CMOS channels per the HSMC specification (only populated when a EP2AGX260 device is installed).
J6	USB type-B connector	USB interface for programming the FPGA through embedded USB-Blaster JTAG via a type-B USB cable.
J8	Gigabit Ethernet	RJ-45 connector which provides a 10/100/1000 Ethernet connection via a Marvell 88E1111 PHY and the FPGA-based Altera Triple Speed Ethernet MegaCore function in RGMII mode.
Display Ports		
J3	Character LCD	Connector which interfaces to the provided 16 character × 2 line LCD module along with two standoffs at MTH7 and MTH8.
Power Supply		
J14	PCI Express edge connector	Interfaces to a PCI Express root port such as an appropriate PC motherboard.
J4	DC input jack	Accepts a 14-V – 20-V DC power supply. This input jack is not to be used while the board is plugged into a PCI Express slot.
SW1	Power switch	Switch to power on or off the board when power is supplied from the DC input jack.

Featured Device: Arria II GX Device

The Arria II GX FPGA development board, 6G Edition features the Arria II GX EP2AGX260FF35 device (U19) in a 1152-pin FBGA package.



For more information about Arria II device family, refer to the [Arria II GX Device Handbook](#).

Table 2-2 describes the features of the Arria II GX EP2AGX260FF35 device.

Table 2-2. Arria II GX Device EP2AGX260FF35 Features

ALMs	Equivalent LEs	M9K RAM Blocks	Total RAM Kbits	18-bit × 18-bit Multipliers	PLLs	Transceivers	Package Type
102,600	244,188	950	11,756	736	6	16	1152-pin FBGA

Table 2-3 lists the Arria II GX component reference and manufacturing information.

Table 2-3. Arria II GX Device Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U19	FPGA, Arria II GX F1152, 260K LEs, leadfree	Altera Corporation	EP2AGX260FF35I3N	www.altera.com

I/O Resources

Figure 2-2 illustrates the bank organization and I/O count for the EP2AGX125 and EP2AGX260 device in the 1152-pin FBGA package.

Figure 2-2. EP2AGX125 and EP2AGX260 Device I/O Bank Diagram

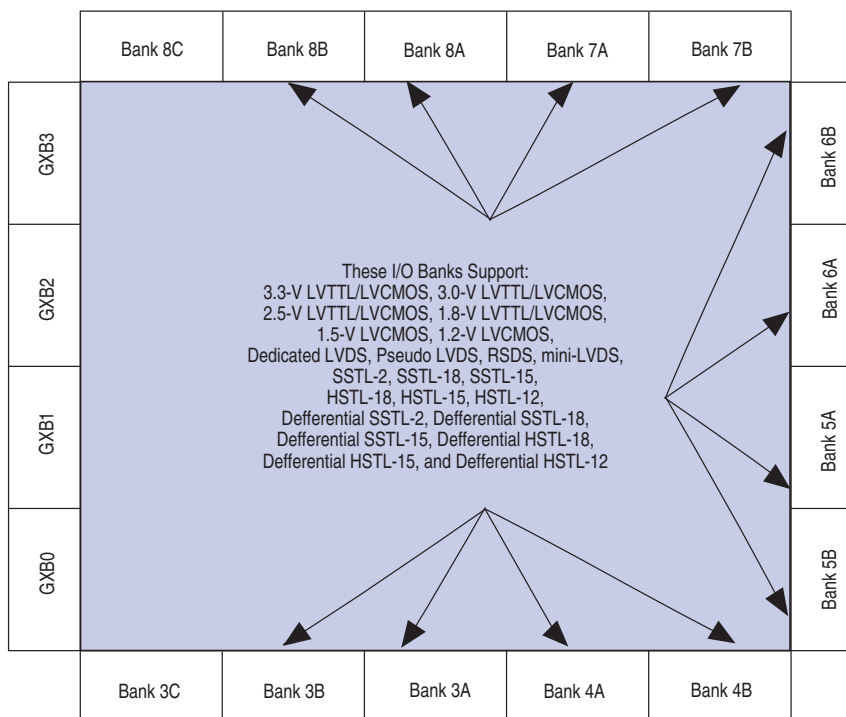


Table 2-4 lists the I/O count for the EP2AGX125 and EP2AGX260 device.

Table 2-4. I/O Count for the EP2AGX125 and EP2AGX260 Device

Package	Device	Bank												Total (1)
		3A	3B	4A	4B	5A	5B	6A	6B	7A	7B	8A	8B	
1152-pin Flip Chip FBGA	EP2AGX125	70	—	74	16	66	—	66	—	70	16	74	—	452
	EP2AGX260	70	32	74	32	66	32	66	32	70	32	74	32	612

Note to Table 2-4:

(1) Transceiver signals are not included.

Table 2-5 lists the Arria II GX device pin count and usage by function on the development board.

Table 2-5. Arria II GX Device Pin Count and Usage

Function	I/O Standard	I/O Count	Special Pins
DDR3 ×16 Port	1.5-V SSTL	49	2 Diff ×8 DQS
DDR2 SODIMM ×64 Port	1.8-V SSTL	120	8 Diff ×8 DQS
MAX Bus	1.5-V CMOS	8	—
Flash, SRAM, FSM Bus	2.5-V CMOS	82	—
PCI Express ×8	2.5-V CMOS + XCVR	41	1 REFCLK, 8 XCVR
HSMC Port A	2.5-V CMOS + LVDS + XCVR	104	4 XCVR, 17 LVDS, 5 Clock Inputs
HSMC Port B (1)	2.5-V CMOS + XCVR	102	4 XCVR, 1 Clock Input
Gigabit Ethernet	2.5-V CMOS + LVDS	16	1 Clock Input
Buttons	1.8-V + 2.5-V CMOS	3	1 DEV_CLRn
Switches	2.5-V CMOS	4	—
LCD	2.5-V CMOS	11	—
LEDs	2.5-V CMOS	7/9 (1)	—
Clocks or Oscillators	2.5-V CMOS + LVDS + LVPECL	13/15 (1)	5 REFCLK
Device I/O Total:		458/564 (1)	

Note to Table 2-5:

(1) The HSMC port B is populated when the board uses an EP2AGX260 device. To support the HSMC port B, there are two additional LEDs and a REFCLK in quadrant 3.

MAX II CPLD EPM2210 System Controller

The board utilizes the EPM2210 System Controller, an Altera MAXII CPLD, for the following purposes:

- FPGA configuration from flash memory
- Power consumption monitoring
- Virtual JTAG interface for PC-based GUI
- Control registers for clocks
- Control registers for remote system update

Figure 2-3 illustrates the MAX II CPLD EPM2210 System Controller's functionality and external circuit connections as a block diagram.

Figure 2-3. MAX II CPLD EPM2210 System Controller Block Diagram

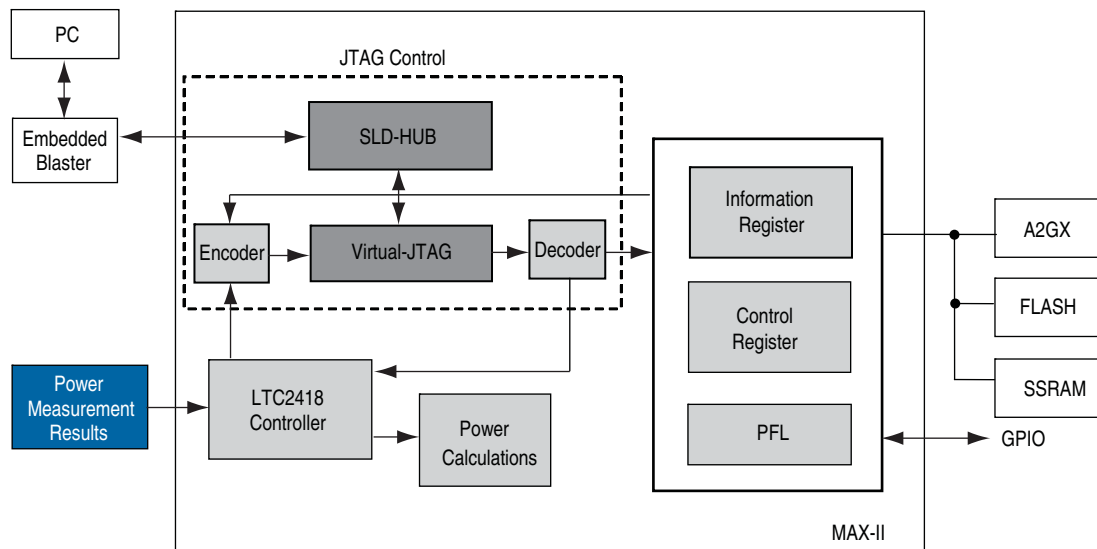


Table 2-6 lists the I/O signals present on the MAX II CPLD EPM2210 System Controller. The signal names and functions are relative to the MAX II device (U32).

Table 2-6. MAX II CPLD EPM2210 System Controller Device Pin-Out (Part 1 of 5)

Schematic Signal Name	I/O Standard	EPM2210 Pin Number	EP2AGX125 Pin Number	Description
clk_enable	2.5-V	K14	—	DIP - clock oscillator enable
clk_sel	2.5-V	P2	—	DIP - clock select SMA or oscillator
clk1_ce	2.5-V	N3	—	Programmable oscillator 1 chip select
clk1_od[0]	2.5-V	M2	—	Programmable oscillator 1 output divider 0
clk1_od[1]	2.5-V	M1	—	Programmable oscillator 1 output divider 1
clk1_od[2]	2.5-V	L3	—	Programmable oscillator 1 output divider 2
clk1_os[0]	2.5-V	N1	—	Programmable oscillator 1 output select 0
clk1_os[1]	2.5-V	N2	—	Programmable oscillator 1 output select 1
clk1_pr[0]	2.5-V	L2	—	Programmable oscillator 1 prescaler 0
clk1_pr[1]	2.5-V	L1	—	Programmable oscillator 1 prescaler 1
clk1_rstn	2.5-V	M3	—	Programmable oscillator 1 reset
clk100_cp1d	2.5-V	H12	—	100 MHz clock input
clk155_oe	2.5-V	E1	—	155.52 MHz oscillator enable
clk2_ce	2.5-V	M14	—	Programmable oscillator 2 chip select
clk2_od[0]	2.5-V	N16	—	Programmable oscillator 2 output divider 0
clk2_od[1]	2.5-V	N14	—	Programmable oscillator 2 output divider 1
clk2_od[2]	2.5-V	N13	—	Programmable oscillator 2 output divider 2

Table 2-6. MAX II CPLD EPM2210 System Controller Device Pin-Out (Part 2 of 5)

Schematic Signal Name	I/O Standard	EPM2210 Pin Number	EP2AGX125 Pin Number	Description
clk2_os[0]	2.5-V	M15	—	Programmable oscillator 2 output select 0
clk2_os[1]	2.5-V	M16	—	Programmable oscillator 2 output select 1
clk2_pr[0]	2.5-V	P15	—	Programmable oscillator 2 prescaler 0
clk2_pr[1]	2.5-V	P14	—	Programmable oscillator 2 prescaler 1
clk2_rstn	2.5-V	N15	—	Programmable oscillator 2 reset
csense_adc_f0	2.5-V	G16	—	Power monitor frequency
csense_csn[0]	2.5-V	J14	—	Power monitor 0 chip select
csense_csn[1]	2.5-V	H15	—	Power monitor 1 chip select
csense_sck	2.5-V	H16	—	Power monitor serial peripheral interface (SPI) clock
csense_sdi	2.5-V	H14	—	Power monitor SPI data in
csense_sdo	2.5-V	H13	—	Power monitor SPI data out
ddr2_scl	2.5-V	M7	—	DDR2 SODIMM EEPROM clock
ddr2_sda	2.5-V	M6	—	DDR2 SODIMM EEPROM data
ep_clk	2.5-V	J15	—	EEPROM clock
ep_cs	2.5-V	J16	—	EEPROM chip select
ep_di	2.5-V	K15	—	EEPROM data in
ep_do	2.5-V	K16	—	EEPROM data out
factory_user	2.5-V	L13	—	Load factory or user design at power-up
flash_advn	2.5-V	C8	T4	FSM bus flash memory address valid
flash_cen	2.5-V	F15	M3	FSM bus flash memory chip enable
flash_clk	2.5-V	C9	N4	FSM bus flash memory clock
flash_oen	2.5-V	E7	K5	FSM bus flash memory output enable
flash_rdy_bsyn	2.5-V	D8	R3	FSM bus flash memory ready
flash_resetsn	2.5-V	D15	N3	FSM bus flash memory reset
flash_wen	2.5-V	D7	C7	FSM bus flash memory write enable
fpga_conf_done	2.5-V	J1	AE25	FPGA configuration done
fpga_config_d[0]	2.5-V	B1	N26	FPGA configuration data
fpga_config_d[1]	2.5-V	A4	N6	FPGA configuration data
fpga_config_d[2]	2.5-V	A7	G2	FPGA configuration data
fpga_config_d[3]	2.5-V	B4	P6	FPGA configuration data
fpga_config_d[4]	2.5-V	B5	L4	FPGA configuration data
fpga_config_d[5]	2.5-V	A6	K3	FPGA configuration data
fpga_config_d[6]	2.5-V	A5	M4	FPGA configuration data
fpga_config_d[7]	2.5-V	B6	K2	FPGA configuration data
fpga_dclk	2.5-V	H4	L25	FPGA configuration clock
fpga_nconfig	2.5-V	J2	AC26	FPGA configuration active
fpga_nstatus	2.5-V	H3	AD28	FPGA configuration ready
fsm_a[0]	2.5-V	A2	M21	FSM bus address

Table 2-6. MAX II CPLD EPM2210 System Controller Device Pin-Out (Part 3 of 5)

Schematic Signal Name	I/O Standard	EPM2210 Pin Number	EP2AGX125 Pin Number	Description
fsm_a[1]	2.5-V	D9	J3	FSM bus address
fsm_a[10]	2.5-V	B16	C24	FSM bus address
fsm_a[11]	2.5-V	C15	E25	FSM bus address
fsm_a[12]	2.5-V	D16	F21	FSM bus address
fsm_a[13]	2.5-V	D10	J19	FSM bus address
fsm_a[14]	2.5-V	A15	H19	FSM bus address
fsm_a[15]	2.5-V	C11	K21	FSM bus address
fsm_a[16]	2.5-V	A12	L21	FSM bus address
fsm_a[17]	2.5-V	B12	F25	FSM bus address
fsm_a[18]	2.5-V	C12	F26	FSM bus address
fsm_a[19]	2.5-V	B13	G23	FSM bus address
fsm_a[2]	2.5-V	E10	D29	FSM bus address
fsm_a[20]	2.5-V	A13	H21	FSM bus address
fsm_a[21]	2.5-V	B14	M13	FSM bus address
fsm_a[22]	2.5-V	D11	P7	FSM bus address
fsm_a[23]	2.5-V	E9	F10	FSM bus address
fsm_a[24]	2.5-V	D6	R4	FSM bus address
fsm_a[25]	2.5-V	C13	K4	FSM bus address
fsm_a[3]	2.5-V	E4	J21	FSM bus address
fsm_a[4]	2.5-V	E5	L13	FSM bus address
fsm_a[5]	2.5-V	E14	C8	FSM bus address
fsm_a[6]	2.5-V	G15	N9	FSM bus address
fsm_a[7]	2.5-V	E15	D20	FSM bus address
fsm_a[8]	2.5-V	F16	A23	FSM bus address
fsm_a[9]	2.5-V	E16	B24	FSM bus address
fsm_d[0]	2.5-V	E11	A19	FSM bus data
fsm_d[1]	2.5-V	E12	C18	FSM bus data
fsm_d[10]	2.5-V	E13	D24	FSM bus data
fsm_d[11]	2.5-V	D13	A25	FSM bus data
fsm_d[12]	2.5-V	C5	B25	FSM bus data
fsm_d[13]	2.5-V	C4	A26	FSM bus data
fsm_d[14]	2.5-V	C7	C26	FSM bus data
fsm_d[15]	2.5-V	C10	A27	FSM bus data
fsm_d[16]	2.5-V	C2	R9	FSM bus data
fsm_d[17]	2.5-V	D3	R10	FSM bus data
fsm_d[18]	2.5-V	E3	R8	FSM bus data
fsm_d[19]	2.5-V	D2	A17	FSM bus data
fsm_d[2]	2.5-V	D12	D28	FSM bus data
fsm_d[20]	2.5-V	E2	D22	FSM bus data

Table 2-6. MAX II CPLD EPM2210 System Controller Device Pin-Out (Part 4 of 5)

Schematic Signal Name	I/O Standard	EPM2210 Pin Number	EP2AGX125 Pin Number	Description
fsm_d[21]	2.5-V	D1	T10	FSM bus data
fsm_d[22]	2.5-V	F1	P4	FSM bus data
fsm_d[23]	2.5-V	F3	R11	FSM bus data
fsm_d[24]	2.5-V	G2	A18	FSM bus data
fsm_d[25]	2.5-V	F2	B18	FSM bus data
fsm_d[26]	2.5-V	G3	C19	FSM bus data
fsm_d[27]	2.5-V	G1	D19	FSM bus data
fsm_d[28]	2.5-V	H1	B21	FSM bus data
fsm_d[29]	2.5-V	G4	A21	FSM bus data
fsm_d[3]	2.5-V	C14	B19	FSM bus data
fsm_d[30]	2.5-V	J4	C21	FSM bus data
fsm_d[31]	2.5-V	H2	A22	FSM bus data
fsm_d[4]	2.5-V	E8	E19	FSM bus data
fsm_d[5]	2.5-V	D4	E18	FSM bus data
fsm_d[6]	2.5-V	C6	G19	FSM bus data
fsm_d[7]	2.5-V	D5	F19	FSM bus data
fsm_d[8]	2.5-V	E6	D21	FSM bus data
fsm_d[9]	2.5-V	D14	D23	FSM bus data
hsma_psnt_n	2.5-V	A10	U3	HSMC port A present
hsmb_psnt_n	2.5-V	J13	AG28	HSMC port B present
led_config_led[0]	2.5-V	B8	—	Flash memory image select indicator
led_config_led[1]	2.5-V	A8	—	Flash memory image select indicator
led_config_led[2]	2.5-V	B7	—	Flash memory image select indicator
factory (IMAGE SEL)	2.5-V	B9	—	Toggles the LED_CONFIG_LED[2:0] sequence.
lcd_pwrmon	2.5-V	K13	—	DIP - MAX II LCD drive enable
reset_confign (LOAD IMAGE)	2.5-V	A9	—	Load the flash memory identified by the configuration LEDs
max_dip[0]	2.5-V	L16	—	DIP - reserved
max_dip[1]	2.5-V	L15	—	DIP - reserved
max_dip[2]	2.5-V	L14	—	DIP - reserved
max_error	2.5-V	B10	—	FPGA configuration error LED
max_led	2.5-V	B11	—	LED - reserved
max_load	2.5-V	A11	—	FPGA configuration active LED
max_resetsn	2.5-V	M9	—	MAX II reset push-button
max2_ben[0]	2.5-V	M11	C15	FSM bus Max2 byte enable 0
max2_ben[1]	2.5-V	M10	H16	FSM bus Max2 byte enable 1
max2_ben[2]	2.5-V	N12	D14	FSM bus Max2 byte enable 2
max2_ben[3]	2.5-V	P12	A9	FSM bus Max2 byte enable 3

Table 2-6. MAX II CPLD EPM2210 System Controller Device Pin-Out (Part 5 of 5)

Schematic Signal Name	I/O Standard	EPM2210 Pin Number	EP2AGX125 Pin Number	Description
max2_clk	2.5-V	N10	J14	FSM bus Max2 clock
max2_csn	2.5-V	M12	A16	FSM bus Max2 chip select
max2_oen	2.5-V	M8	A14	FSM bus Max2 output enable
max2_wen	2.5-V	N11	B16	FSM bus Max2 write enable
sram_mode	2.5-V	J3	—	FSM bus SSRAM burst sequence selection
sram_zz	2.5-V	B3	B27	FSM bus SSRAM power sleep mode
usb_disablen	2.5-V	K2	—	DIP - embedded USB-Blaster disable
usb_led	2.5-V	K1	—	Embedded USB-Blaster active

Table 2-7 lists the MAX II CPLD EPM2210 System Controller component reference and manufacturing information.

Table 2-7. MAX II CPLD EPM2210 System Controller Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U32	IC - MAX II CPLD EPM2210 256FBGA -3 LF 2.5V VCCINT	Altera Corporation	EPM2210F256C3N	www.altera.com

Configuration, Status, and Setup Elements

This section describes the board's configuration, status, and setup elements.

Configuration

This section describes the FPGA, flash memory, and MAX II CPLD EPM2210 System Controller device programming methods supported by the Arria II GX FPGA development board, 6G Edition. The Arria II GX FPGA development board, 6G Edition supports the following three configuration methods:

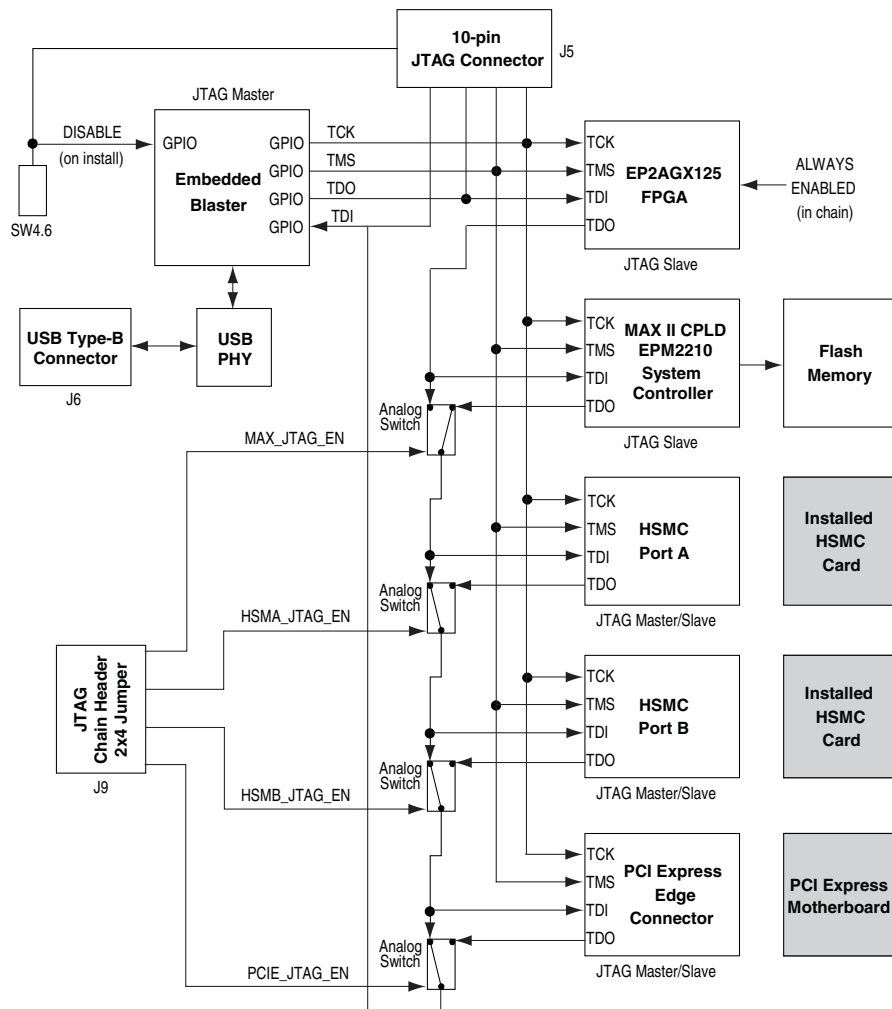
- Embedded USB-Blaster is the default method for configuring the FPGA at any time using the Quartus II Programmer in JTAG mode with the supplied USB cable.
- External USB-Blaster for configuring the FPGA using the external USB-Blaster.
- Flash memory download is used for configuring the FPGA using stored images from the flash memory on either power-up or pressing the LOAD IMAGE push-button switch (PB5).

FPGA Programming over Embedded USB-Blaster

The USB-Blaster is implemented using a USB Type-B connector (J6), a FTDI USB 2.0 PHY device (U15), and an Altera MAX II CPLD (U32). This allows the configuration of the FPGA using a USB cable directly connected between the USB port on the board (J6) and a USB port of a PC running the Quartus II software. The JTAG chain is normally mastered by the embedded USB-Blaster found in the MAX II CPLD EPM240Z.

The embedded USB-Blaster is automatically disabled when an external USB-Blaster is connected to the JTAG chain. Figure 2-4 illustrates the JTAG chain.

Figure 2-4. JTAG Chain



Each jumper shown in Figure 2-4 is located in the JTAG chain header (J9) on the front of the board. To connect a device or interface in the chain, the corresponding shunt must be removed from the jumper. Install a shunt on each of the four jumper positions to only have the FPGA in the chain.

The MAX II CPLD EPM2210 System Controller must be in the chain to use some of the GUI interfaces. For this setting, remove the left-most jumper shunt from the JTAG chain header (J9).

Flash Memory Programming

Flash memory programming is possible through a variety of methods using the Arria II GX device.

The default method is to use the factory design called the Board Update Portal. This design is an embedded webserver, which serves the Board Update Portal web page. The web page allows you to select new FPGA designs including hardware, software, or both in an industry-standard S-Record File (**.flash**) and write the design to the user hardware page (page 1) of the flash memory over the network.

The secondary method is to use the pre-built parallel flash loader (PFL) design included in the development kit. The development board implements the Altera PFL megafunction for flash memory programming. The PFL megafunction is a block of logic that is programmed into an Altera programmable logic device (FPGA or CPLD). The PFL functions as a utility for writing to a compatible flash memory device. This pre-built design contains the PFL megafunction that allows you to write either page 0, page 1, or other areas of flash memory over the USB interface using the Quartus II software. This method is used to restore the development board to its factory default settings.

Other methods to program the flash memory can be used as well, including the Nios® II processor.



For more information on the Nios II processor, refer to the [Nios II Processor](#) page of the Altera website.

FPGA Programming from Flash Memory

On either power-up or by pressing the load image push-button switch (PB5), the MAX II CPLD EPM2210 System Controller's PFL configures the FPGA from the flash memory when the CONFIG_LED0 is ON. The PFL megafunction reads 16-bit data from the flash memory and converts it to fast passive parallel (FPP) format. This 8-bit data is then written to the FPGA's dedicated configuration pins during configuration.

Table 2–8 shows the flash memory map storage.

Table 2–8. Flash Memory Map

Name	Size (Kbyte)	Address
Unused	32	0x03FF.FFFF 0x03FF.8000
	32	0x03FF.7FFF 0x03FF.0000
	32	0x03FE.FFFF 0x03FE.8000
	32	0x03FE.7FFF 0x03FE.0000
User software	16,384	0x03FD.FFFF 0x0300.0000
Factory software	8,192	0x02FF.FFFF 0x0280.0000
zipfs—HTML, web content	8,192	0x027F.FFFF 0x0200.0000
User hardware 2	11,141	0x01FF.FFFF 0x0156.0000
User hardware 1	11,141	0x0155.FFFF 0x00AC.0000
Factory hardware	11,141	0x00AB.FFFF 0x0002.0000
PFL option bits	32	0x0001.FFFF 0x0001.8000
Board information	32	0x0001.7FFF 0x0001.0000
Ethernet option bits (MAC address)	32	0x0000.FFFF 0x0000.8000
User design reset vector	32	0x0000.7FFF 0x0000.0000

There are two pages reserved for the FPGA configuration data. The factory hardware page is considered page 0 and is loaded upon power-up if the USER_LOAD DIP switch (SW4.4) is set to '1'. Otherwise, the user hardware page 1 is loaded. Pressing the load image push-button switch (PB5) loads the FPGA with a hardware page based on which CONFIG[2:0] LED (D11, D12, D13) is illuminated. Table 2–9 defines the hardware page that loads when the load image push-button switch (PB5) is pressed.

Table 2-9. Load Image Push-Button Switch (PB5) LED Settings (1) (2)

IMAGE0	IMAGE1	IMAGE2	Design
ON	OFF	OFF	Factory hardware
OFF	ON	OFF	User hardware 1
OFF	OFF	ON	User hardware 2

Notes to Table 2-9:

- (1) ON indicates a setting of '1'.
 (2) OFF indicates a setting of '0'.

FPGA Programming over External USB-Blaster

The JTAG programming header provides another method for configuring the FPGA (U19) using an external USB-Blaster device with the Quartus II Programmer running on a PC. The external USB-Blaster is connected to the board through the JTAG connector (J5). Install a shunt onto the JTAG chain header (J9) pins 1 and 2 to remove the MAX II CPLD device from the JTAG chain so that the FPGA is the only device on the JTAG chain.



For more information on the following topics, refer to the respective documents:

- Board Update Portal, refer to the *Arria II GX FPGA Development Kit, 6G Edition User Guide*.
- PFL design, refer to the *Arria II GX FPGA Development Kit, 6G Edition User Guide*.
- PFL megafunction, refer to *Parallel Flash Loader Megafunction User Guide*.

Status Elements

The development board includes status LEDs. This section describes the status elements.

Table 2-10 lists the LED board references, names, and functional descriptions.

Table 2-10. Board-Specific LEDs (Part 1 of 2)

Board Reference	LED Name	Description
D18	Power	Blue LED. Illuminates when 2.5 V power is active.
D14	CONF DONE	Green LED. Illuminates when the FPGA is successfully configured. Driven by the MAX II CPLD EPM2210 System Controller.
D15	Loading	Green LED. Illuminates when the MAX II CPLD EPM2210 System Controller is actively configuring the FPGA. Driven by the MAX II CPLD EPM2210 System Controller wire-OR'd with the embedded USB-Blaster CPLD.
D16	Error	Red LED. Illuminates when the MAX II CPLD EPM2210 System Controller fails to configure the FPGA. Driven by the MAX II CPLD EPM2210 System Controller.
D11, D12, D13	CONFIG[2:0]	Green LEDs. Illuminates to indicate which hardware page loads from flash memory.
D19	ENET TX	Green LED. Illuminates to indicate Ethernet PHY transmit activity. Driven by the Marvell 88E1111 PHY.
D20	ENET RX	Green LED. Illuminates to indicate Ethernet PHY receive activity. Driven by the Marvell 88E1111 PHY.

Table 2-10. Board-Specific LEDs (Part 2 of 2)

Board Reference	LED Name	Description
D23	10	Green LED. Illuminates to indicate Ethernet linked at 10 Mbps connection speed. Driven by the Marvell 88E1111 PHY.
D22	100	Green LED. Illuminates to indicate Ethernet linked at 100 Mbps connection speed. Driven by the Marvell 88E1111 PHY.
D21	1000	Green LED. Illuminates to indicate Ethernet linked at 1000 Mbps connection speed. Driven by the Marvell 88E1111 PHY.
D6	HSMC Port A Present	Green LED. Illuminates when HSMC port A has a board or cable plugged-in such that pin 160 becomes grounded. Driven by the add-in card.
D1	HSMC Port B Present	Green LED. Illuminates when HSMC port B has a board or cable plugged-in such that pin 160 becomes grounded. Driven by the add-in card.
D24	PCIe x1	Green LED. Configure this LED to display the PCI Express link width x1.
D25	PCIe x4	Green LED. Configure this LED to display the PCI Express link width x4.
D26	PCIe x8	Green LED. Configure this LED to display the PCI Express link width x8.

Table 2-11 lists the board-specific LEDs component references and manufacturing information.

Table 2-11. Board-Specific LEDs Component References and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
D1, D6, D11-D16, D19-D26	Green LEDs	Lite-On	LTST-C170KGKT	www.us.liteon.com/opto.index.html
D16	Red LED	Lite-On	LTST-C170KRKT	www.us.liteon.com/opto.index.html
D18	Blue LED	Lite-On	LTST-C170TBKT	www.us.liteon.com/opto.index.html

Setup Elements

The development board includes several different kinds of setup elements. This section describes the following setup elements:

- Board settings DIP switch
- JTAG chain header switch
- PCI Express control DIP switch
- Reset configuration push-button switches

Board Settings DIP Switch

The board settings DIP switch (SW4) controls various features specific to the board and the MAX II CPLD EPM2210 System Controller logic design. Table 2-12 shows the switch controls and descriptions.

Table 2-12. Board Settings DIP Switch Controls (Part 1 of 2)

Switch	Schematic Signal Name	Description	Default
1	MAX_DIP0	Reserved	OFF
2	MAX_DIP1	Reserved	OFF

Table 2-12. Board Settings DIP Switch Controls (Part 2 of 2)

Switch	Schematic Signal Name	Description	Default
3	MAX_DIP2	Reserved	OFF
4	MAX_DIP3	ON : Load User hardware page 1 from flash memory upon power-up OFF : Load factory design from flash memory upon power-up	OFF
5	LCD_PWRMON	ON : LCD driven from the MAX II EPM2210 System Controller (power monitor) OFF : Unused	ON
6	USB_DISABLEn	ON : Embedded USB-Blaster disable OFF : Embedded USB-Blaster enable	OFF
7	CLK_ENABLE	ON : On-board oscillators enable OFF : On-board oscillators disable	ON
8	CLK_SEL	ON : 100 MHz clock select OFF : SMA input clock select	ON

Table 2-13 lists the board settings DIP switch component reference and manufacturing information.

Table 2-13. Board Settings DIP Switch Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
SW4	Eight-position slide DIP switch	HCH	HPS608-E	www.hchtn.com.tw

JTAG Chain Header Switch

The JTAG chain header switch (J9) is provided to either remove or include devices in the active JTAG chain. However, the Arria II GX FPGA device is always in the JTAG chain. Table 2-14 shows the switch controls and its descriptions.

Table 2-14. JTAG Chain Header Switch Controls

Switch	Schematic Signal Name	Description	Default
1	MAX_JTAG_EN	ON : Bypass MAX II CPLD EPM2210 System Controller OFF : MAX II CPLD EPM2210 System Controller in-chain	ON
2	HSMA_JTAG_EN	ON : Bypass HSMA OFF : HSMA in-chain	ON
3	HSMB_JTAG_EN	ON : Bypass HSMB OFF : HSMB in-chain	ON
4	PCIE_JTAG_EN	ON : Bypass PCI Express OFF : Reserved (disables JTAG chain, do not use)	ON

Table 2-15 lists the JTAG chain header switch component reference and manufacturing information.

Table 2-15. JTAG Chain Header Switch Component Reference and Manufacturing Information

Board Reference	Device Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
J9	2x4 100 mil jumper	Leamax Enterprise Co.	21312*4SE	www.leafmax.com

PCI Express Control DIP Switch

The PCI Express control DIP switch (SW3) is provided to enable or disable different configurations. Table 2-16 shows the switch controls and descriptions.

Table 2-16. PCI Express Control DIP Switch Controls

Switch	Schematic Signal Name	Description	Default
1	PCIE_PRSENT2n_x1	ON : Enable x1 presence detect OFF : Disable x1 presence detect	ON
2	PCIE_PRSENT2n_x4	ON : Enable x4 presence detect OFF : Disable x4 presence detect	ON
3	PCIE_PRSENT2n_x8	ON : Enable x8 presence detect OFF : Disable x8 presence detect	ON
4	NC	Not used	OFF

Table 2-17 lists the PCI Express control DIP switch component reference and manufacturing information.

Table 2-17. PCI Express Control DIP Switch Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
SW3	Four-position slide DIP switch	HCH	HPS604-E	www.hchtwn.com.tw

Reset Configuration Push-button Switches

The load image push-button switch, RESET_CONFIGn (LOAD IMAGE) (PB5), is an input to the MAX II CPLD EPM2210 System Controller. The push-button switch forces a reconfiguration of the FPGA from flash memory. The location in the flash memory is based on the LED_CONFIG_LED[2:0] setting when the button is released. Valid settings include LED_CONFIG_LED0, LED_CONFIG_LED1, or LED_CONFIG_LED2 on the three pages in flash memory reserved for FPGA designs.

The image select push-button switch, factory (IMAGE SEL) (PB6), toggles the LED_CONFIG_LED[2:0] sequence. Refer to Table 2-9 for the LED_CONFIG_LED[2:0] sequence definitions.

The MAX II reset push-button switch, MAX_RESETn (PB4), resets the MAX II CPLD EPM2210 System Controller.

Table 2-18 lists the reset configuration push-button switches component reference and manufacturing information.

Table 2-18. Reset Configuration Push-button Switches Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
PB4, PB5, PB6	Push-button Switch	Dawning Precision Co.	TS-A02SA-2-S100	http://www.dawning2.com.tw/company.php

Clock Circuitry

This section describes the board's clock inputs and outputs.

Arria II GX FPGA Clock Inputs

The development board has two types of clock inputs: global clock inputs and transceiver reference clock inputs.

Figure 2-6 shows the Arria II GX FPGA development board, 6G Edition clock inputs.

Figure 2-6. Arria II GX FPGA Development Board, 6G Edition Clock Inputs

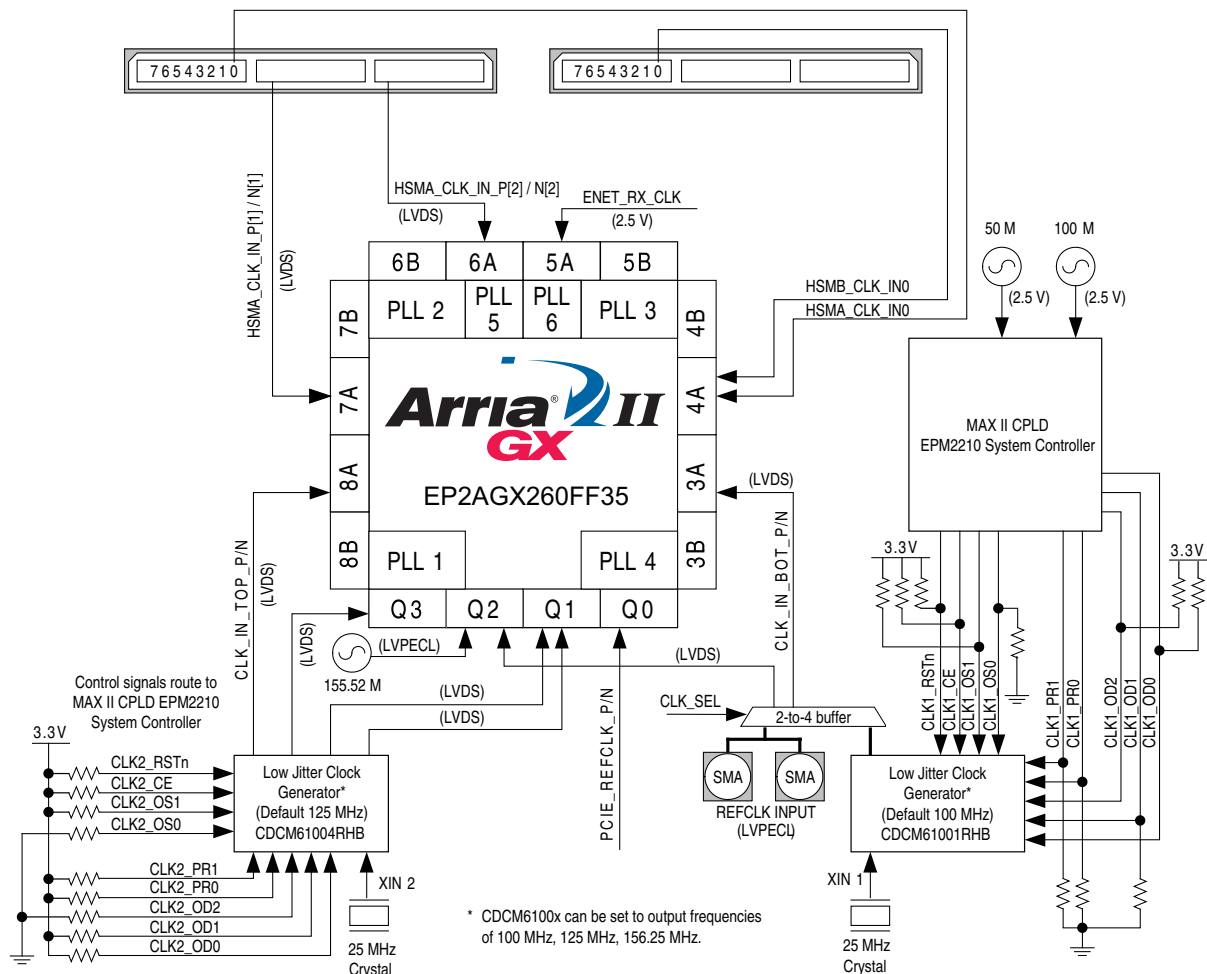


Table 2-19 shows the external clock inputs for the Arria II GX FPGA development board, 6G Edition.

Table 2-19. Arria II GX FPGA Development Board, 6G Edition Clock Inputs

Source	Schematic Signal Name	Pin	I/O Standard	Description
U25	CLK_155_P	R29	LVPECL	155.52 MHz oscillator which drives the transceiver Q2 reference clock input with 100 Ω OCT.
	CLK_155_N	R30		
SMA or 100.000 MHz (Default Frequency) (1)	CLKIN_BOT_P	AJ19	LVDS	Input to the fan-out buffer (U33) which drives LVDS input to the bottom edge of PLL input.
	CLKIN_BOT_N	AK19		
	CLKIN_REF_Q2_P	U29		Input to the fan-out buffer (U33) which drives LVDS input to the transceiver Q2 reference clock input with 100 Ω OCT.
	CLKIN_REF_Q2_N	U30		
125.000 MHz (Default Frequency) (2)	CLKIN_TOP_P	F18	LVDS	Programmable oscillator which drives LVDS input to the top edge of PLL input.
	CLKIN_TOP_N	F17		
	CLK_REF_Q1_1_P	AA29		Programmable oscillator which drives LVDS input to the transceiver Q1 reference clock input with 100 Ω OCT.
	CLK_REF_Q1_1_N	AA30		
	CLK_REF_Q1_2_P	W29		Programmable oscillator which drives LVDS input to the transceiver Q3 reference clock input with 100 Ω OCT.
	CLK_REF_Q1_2_N	W30		
	CLK_REF_Q3_P	N29		
	CLK_REF_Q3_N	N30		
Samtec HSMC	HSMA_CLKIN0	AP17	LVTTTL	Single-ended input from the installed HSMC port A cable or board.
Samtec HSMC	HSMA_CLKIN_P1	U6	LVDS or LVTTTL	LVDS input from the installed HSMC port A cable or board. Can also support two LVTTTL inputs.
	HSMA_CLKIN_N1	U5		
Samtec HSMC	HSMA_CLKIN_P2	K18	LVDS or LVTTTL	LVDS input from the installed HSMC port A cable or board. Can also support two LVTTTL inputs.
	HSMA_CLKIN_N2	J18		
Samtec HSMC	HSMB_CLKIN0	AP16	LVTTTL	Single-ended input from the installed HSMC port B cable or board.
PCI Express Edge	PCIE_REFCLK_P	AE29	HCSL	High-Speed Current Steering Logic (HCSL) input from the PCI Express edge connector.
	PCIE_REFCLK_N	AE30		

Notes to Table 2-19:

- (1) CDCM61001 has a default frequency of 100 MHz, but can also be set by the MAX II CPLD to frequencies of 125 MHz and 156.25 MHz.
- (2) CDCM61004 has a default frequency of 125 MHz, but can also be set by the MAX II CPLD to frequencies of 100 MHz and 156.25 MHz.

Table 2-21 lists the crystal oscillators component references and manufacturing information.

Table 2-21. Crystal Oscillator Component References and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
U25	156.25 MHz LVPECL Saw Oscillator	Epson	EG-2102CA 155.5200M-DGPA	www.eea.epson.com
U26	Quad Output Programmable Clock Generator	Texas Instruments	CDCM61004RHBR	www.ti.com
U30	Single Output Programmable Clock Generator	Texas Instruments	CDCM61001RHBR	www.ti.com
Y6	100 MHz Crystal Oscillator	Mercury Electronics	3H53-AT-100.000	www.mecxtal.com
Y5	50 MHz Crystal Oscillator	Epson	XG-1000CB 50.0000M-DCL3	www.eea.epson.com

General User Input/Output

This section describes the user I/O interface to the FPGA, including the push-buttons, DIP switches, status LEDs, and character LCD.

User-Defined Push-Button Switches

The development board includes three user-defined push-button switches: two general user push-button switches and one CPU reset. For information on the system and safe reset push-button switches, refer to “Reset Configuration Push-button Switches” on page 2-19.

Board references PB1 and PB2 are push-button switches that allow you to interact with the Arria II GX device. When the switch is pressed and held down, the device pin is set to logic 0; when the switch is released, the device pin is set to logic 1. There is no board-specific function for these general user push-button switches.

The board reference PB3 is the CPU reset push-button switch, CPU_RESET, which is an input to the Arria II GX device. CPU_RESET is intended to be the master reset signal for the FPGA design loaded into the Arria II GX device. It also acts as a regular I/O pin.

Table 2-22 lists the user-defined push-button switch schematic signal names and their corresponding Arria II GX device pin numbers.

Table 2-22. User-defined Push-button Switch Schematic Signal Names and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
PB2	User-defined push-button switch	USER_PB0	1.8-V	AK9
PB1		USER_PB1		AL7
PB3		CPU_RESET	2.5-V	N10

Table 2–23 lists the user-defined push-button switch component reference and the manufacturing information.

Table 2–23. User-defined Push-button Switch Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
PB1 to PB3	Push-button switch	Dawning Precision Co.	TS-A02SA-2-S100	http://www.dawning2.com.tw/company.php

User-Defined DIP Switches

Board reference SW2 is a 4-pin DIP switch. The switches in SW2 are user-defined and provided for additional FPGA input control. There is no board-specific function for these switches.

Table 2–24 lists the user-defined DIP switch schematic signal names and their corresponding Arria II GX pin numbers.

Table 2–24. User-defined DIP Switch Schematic Signal Names and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
SW2.1	User-defined DIP switch connected to the FPGA device. When the switch is in the OFF position, a logic 1 is selected. When the switch is in the ON position, a logic 0 is selected.	USER_DIP0	2.5-V	N2
SW2.2		USER_DIP1		U9
SW2.3		USER_DIP2		V9
SW2.4		USER_DIP3		U4

Table 2–25 lists the user-defined DIP switch component reference and the manufacturing information.

Table 2–25. User-defined DIP Switch Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
SW2	Four-position DIP switch	HCH	HPS604-E	www.hchtwn.com.tw

User-Defined LEDs

The development board includes general and HSMC user-defined LEDs. This section describes all user-defined LEDs. For information on board specific or status LEDs, refer to “Status Elements” on page 2–16.

General User-Defined LEDs

Board references D7 through D10 are four user-defined LEDs which allow status and debugging signals to be driven to the LEDs from the FPGA designs loaded into the Arria II GX device. The LEDs illuminate when a logic 0 is driven, and turns off when a logic 1 is driven. There is no board-specific function for these LEDs.

Table 2–26 lists the user-defined LED schematic signal names and their corresponding Arria II GX pin numbers.

Table 2–26. User-defined LED Schematic Signal Names and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
D10	User-defined LEDs. Driving a logic 0 on the I/O port turns the LED ON. Driving a logic 1 on the I/O port turns the LED OFF.	USR_LED0	2.5-V	G1
D9		USR_LED1		J4
D8		USR_LED2		J5
D7		USR_LED3		R5

Table 2–27 lists the user-defined LED component reference and the manufacturing information.

Table 2–27. User-defined LED Component Reference and Manufacturing Information

Board Reference	Device Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
D7 to D10	Green LEDs	Lite-On	LTST-C170KGKT	www.us.liteon.com/opto.index.html

HSMC User-Defined LEDs

The HSMC port A and B have two LEDs located nearby. There are no board-specific functions for the HSMC LEDs. However, the LEDs are labeled TX and RX, and are intended to display data flow to and from the connected HSMC daughtercards. The LEDs are driven by the Arria II GX device.

Table 2–28 lists the HSMC user-defined LED schematic signal names and their corresponding Arria II GX pin numbers.

Table 2–28. HSMC User-defined LED Schematic Signal Names and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
D5	User-defined LEDs. Labeled TX for HSMC port A.	HSMA_TX_LED	2.5-V	C29
D4	User-defined LEDs. Labeled RX for HSMC port A.	HSMA_RX_LED		N5
D3	User-defined LEDs. Labeled TX for HSMC port B.	HSMB_TX_LED		AE24
D2	User-defined LEDs. Labeled RX for HSMC port B.	HSMB_RX_LED		AF23

Table 2–29 lists the HSMC user-defined LED component reference and the manufacturing information.

Table 2–29. HSMC User-defined LED Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
D2 to D5	Green LEDs	Lite-On	LTST-C170KGKT	www.us.liteon.com/opto.index.html

LCD

The development board contains a single 14-pin 0.1" pitch dual-row header that interfaces to a 16 character × 2 line Lumex LCD display. The LCD has a 14-pin receptacle that mounts directly to the board's 14-pin header, so it can be easily removed for access to components under the display. You can also use the header for debugging or other purposes.

Table 2–30 summarizes the LCD pin assignments. The signal names and directions are relative to the Arria II GX FPGA.

Table 2–30. LCD Pin Assignments, Schematic Signal Names, and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J3.7	LCD data bus	LCD_DATA0	2.5-V	F1
J3.8	LCD data bus	LCD_DATA1		H3
J3.9	LCD data bus	LCD_DATA2		E1
J3.10	LCD data bus	LCD_DATA3		F2
J3.11	LCD data bus	LCD_DATA4		D2
J3.12	LCD data bus	LCD_DATA5		D1
J3.13	LCD data bus	LCD_DATA6		C2
J3.14	LCD data bus	LCD_DATA7		C1
J3.4	LCD data or command select	LCD_D_Cn		J1
J3.5	LCD write enable	LCD_WEn		H1
J3.6	LCD chip select	LCD_CSn		J2

Table 2–31 shows the LCD pin definitions, and is an excerpt from the Lumex data sheet.



For more information such as timing, character maps, interface guidelines, and other related documentation, visit www.lumex.com.

Table 2–31. LCD Pin Definitions and Functions (Part 1 of 2)

Pin Number	Symbol	Level	Function	
1	V _{DD}	—	Power supply	5 V
2	V _{SS}	—		GND (0 V)
3	V ₀	—		For LCD drive

Table 2-31. LCD Pin Definitions and Functions (Part 2 of 2)

Pin Number	Symbol	Level	Function
4	RS	H/L	Register select signal H: Data input L: Instruction input
5	R/W	H/L	H: Data read (module to MPU) L: Data write (MPU to module)
6	E	H, H to L	Enable
7-14	DB0-DB7	H/L	Data bus, software selectable 4-bit or 8-bit mode

Table 2-32 lists the LCD component references and the manufacturing information.

Table 2-32. LCD Component References and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturer Part Number	Manufacturer Website
J3	2×7 pin, 100 mil, vertical header	Samtec	TSM-107-01-G-DV	www.samtec.com
	2×16 character display, 5×8 dot matrix	Lumex Inc.	LCM-S01602DSR/C	www.lumex.com

Components and Interfaces

This section describes the development board's communication ports and interface cards relative to the Arria II GX device. The development board supports the following communication ports:

- PCI Express
- 10/100/1000 Ethernet
- HSMC

PCI Express

The Arria II GX FPGA development board, 6G Edition is designed to fit entirely into a PC motherboard with a ×8 PCI Express slot that can accommodate a full height long form factor add-in card. This interface uses the Arria II GX device's PCI Express hard IP block, saving logic resources for the user logic application.



For more information on using the PCI Express hard IP block, refer to the *PCI Express Compiler User Guide*.

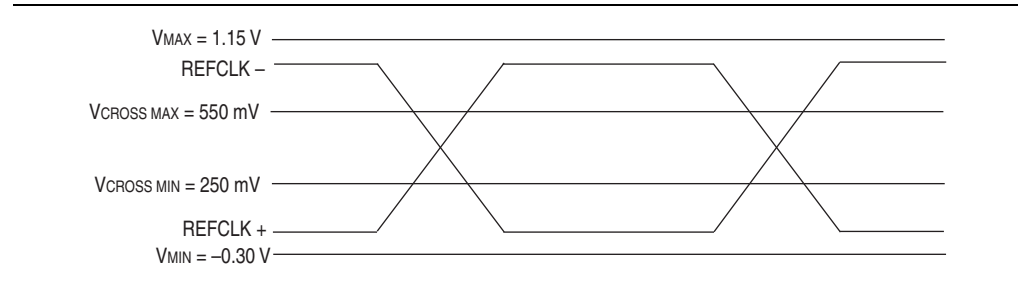
The PCI Express interface supports auto-negotiating channel width from ×1 to ×4 to ×8 as well as the connection speed of Gen1 at 2.5 Gbps/lane for a maximum of 20 Gbps full-duplex.

The power for the board can be sourced entirely from the PCI Express edge connector when installed into a PC motherboard. Although the board can also be powered by a laptop power supply for use on a lab bench, it is not recommended to power from both supplies at the same time. Ideal diode power sharing devices have been designed into this board to prevent damages or back-current from one supply to the other.

The PCIE_REFCLK_P signal is a 100 MHz differential input that is driven from the PC motherboard on to this board through the edge connector. This signal is connected directly to a Arria II GX REFCLK input pin pair using DC coupling. This clock is terminated on the motherboard and therefore, no on-board termination is required. This clock can have spread-spectrum properties that change its period between 9.847 ps to 10.203 ps. The I/O standard is HCSL.

Figure 2-8 shows the PCI Express reference clock levels.

Figure 2-8. PCI Express Reference Clock Levels



The JTAG and SMB are optional signals in the PCI Express specification. Both types of signals are wired to the Arria II GX device but are not required for normal operation. The PCI Express control DIP switch allows the presence detect grounding to be altered to enable a $\times 1$, $\times 4$, or $\times 8$ width edge connector. The PCI Express control DIP switch does not support auto-negotiation.

Table 2-33 summarizes the PCI Express pin assignments. The signal names and directions are relative to the Arria II GX FPGA.

Table 2-33. PCI Express Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J14.B14	Add-in card receive bus	PCIE_RX_P0	1.5-V PCML	AN33
J14.B15	Add-in card receive bus	PCIE_RX_N0		AN34
J14.B19	Add-in card receive bus	PCIE_RX_P1		AL33
J14.B20	Add-in card receive bus	PCIE_RX_N1		AL34
J14.B23	Add-in card receive bus	PCIE_RX_P2		AJ33
J14.B24	Add-in card receive bus	PCIE_RX_N2		AJ34
J14.B27	Add-in card receive bus	PCIE_RX_P3		AG33
J14.B28	Add-in card receive bus	PCIE_RX_N3		AG34
J14.B33	Add-in card receive bus	PCIE_RX_P4		AE33
J14.B34	Add-in card receive bus	PCIE_RX_N4		AE34

Table 2-33. PCI Express Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J14.B37	Add-in card receive bus	PCIE_RX_P5	1.5-V PCML	AC33
J14.B38	Add-in card receive bus	PCIE_RX_N5		AC34
J14.B41	Add-in card receive bus	PCIE_RX_P6		AA33
J14.B42	Add-in card receive bus	PCIE_RX_N6		AA34
J14.B45	Add-in card receive bus	PCIE_RX_P7		W33
J14.B46	Add-in card receive bus	PCIE_RX_N7		W34
J14.A16	Add-in card transmit bus	PCIE_TX_P0		AM31
J14.A17	Add-in card transmit bus	PCIE_TX_N0		AM32
J14.A21	Add-in card transmit bus	PCIE_TX_P1		AK31
J14.A22	Add-in card transmit bus	PCIE_TX_N1		AK32
J14.A25	Add-in card transmit bus	PCIE_TX_P2		AH31
J14.A26	Add-in card transmit bus	PCIE_TX_N2		AH32
J14.A29	Add-in card transmit bus	PCIE_TX_P3		AF31
J14.A30	Add-in card transmit bus	PCIE_TX_N3		AF32
J14.A35	Add-in card transmit bus	PCIE_TX_P4		AD31
J14.A36	Add-in card transmit bus	PCIE_TX_N4		AD32
J14.A39	Add-in card transmit bus	PCIE_TX_P5		AB31
J14.A40	Add-in card transmit bus	PCIE_TX_N5		AB32
J14.A43	Add-in card transmit bus	PCIE_TX_P6		Y31
J14.A44	Add-in card transmit bus	PCIE_TX_N6		Y32
J14.A47	Add-in card transmit bus	PCIE_TX_P7		V31
J14.A48	Add-in card transmit bus	PCIE_TX_N7		V32
J14.A13	Motherboard reference clock	PCIE_REFCLK_P	HCSL	AE29
J14.A14	Motherboard reference clock	PCIE_REFCLK_N		AE30
J14.A11	Reset	PCIE_PERSTn	LVTTTL	N1
J14.B11	Wake signal	PCIE_WAKEn		C30
J14.B5	SMB clock	PCIE_SMBCLK		M18
J14.B6	SMB data	PCIE_SMBDAT		D27
—	x1 Presence detect	PCIE_LED_X1		C28
—	x4 Presence detect	PCIE_LED_X4		D26
—	x8 Presence detect	PCIE_LED_X8		C27

10/100/1000 Ethernet

A Marvell 88E1111 PHY device is used for 10/100/1000 BASE-T Ethernet connection. The device is an auto-negotiating Ethernet PHY with an RGMII interface to the FPGA. The MAC function must be provided in the FPGA for typical networking applications. The Marvell 88E1111 PHY uses 2.5-V and 1.0-V power rails and requires a 25 MHz reference clock driven from a dedicated oscillator. It interfaces to a HALO HFJ11-1G02E model RJ45 with internal magnetics that can be used for driving copper lines with Ethernet traffic.

Figure 2-9 shows the RGMII interface between the FPGA (MAC) and Marvell 88E1111 PHY.

Figure 2-9. RGMII Interface between FPGA (MAC) and Marvell 88E1111 PHY

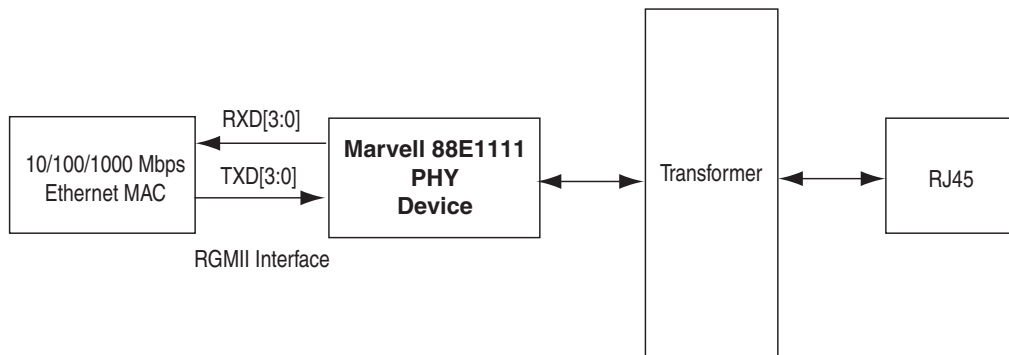


Table 2-34 lists the Ethernet PHY interface pin assignments.

Table 2-34. Ethernet PHY Pin Assignments, Signal Names and Functions

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U24.8	RGMII transmit clock	ENET_GTX_CLK	2.5-V	D25
U24.23	Management bus interrupt	ENET_INTn		D18
U24.25	Management bus control	ENET_MDC		K20
U24.24	Management bus data	ENET_MDIO		N20
U24.28	Device reset	ENET_RESETn		M20
U24.2	RGMII receive clock	ENET_RX_CLK		V6
U24.95	RGMII receive data	ENET_RXD[0]		E21
U24.92	RGMII receive data	ENET_RXD[1]		E24
U24.93	RGMII receive data	ENET_RXD[2]		E22
U24.91	RGMII receive data	ENET_RXD[3]		F24
U24.94	RGMII receive control	ENET_RX_DV		D17
U24.11	RGMII transmit data	ENET_TXD[0]		J20
U24.12	RGMII transmit data	ENET_TXD[1]		C25
U24.14	RGMII transmit data	ENET_TXD[2]		G22
U24.16	RGMII transmit data	ENET_TXD[3]		G21
U24.9	RGMII transmit control	ENET_TX_EN		G20

Table 2-35 lists the Ethernet PHY interface component reference and manufacturing information.

Table 2-35. Ethernet PHY Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U24	Ethernet PHY BASE-T device	Marvell Semiconductor	88E1111-B2-CAAIC000	www.marvell.com

High-Speed Mezzanine Cards

The development board contains two HSMC interfaces called port A and port B. The HSMC port B is only available in the Arria II GX FPGA development board, 6G Edition. HSMC port A interface supports both single-ended and differential signaling while HSMC port B interface only supports single-ended signaling. The HSMC interface also allows JTAG, SMB, clock outputs and inputs, as well as power for compatible HSMC cards. The HSMC is an Altera-developed open specification, which allows you to expand the functionality of the development board through the addition of daughtercards (HSMCs).

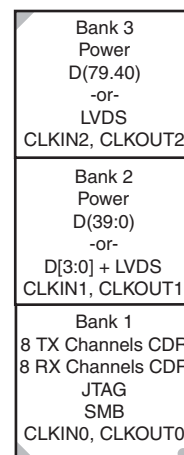


For more information about the HSMC specification such as signaling standards, signal integrity, compatible connectors, and mechanical information, refer to the *High Speed Mezzanine Card (HSMC) Specification* manual.

The HSMC connector has a total of 172 pins, including 120 signal pins, 39 power pins, and 13 ground pins. The ground pins are located between the two rows of signal and power pins, acting both as a shield and a reference. The HSMC host connector is based on the 0.5 mm-pitch QSH/QTH family of high-speed, board-to-board connectors from Samtec. There are three banks in this connector. Bank 1 has every third pin removed as done in the QSH-DP/QTH-DP series. Bank 2 and bank 3 have all the pins populated as done in the QSH/QTH series.

Figure 2-10 shows the bank arrangement of signals with respect to the Samtec connector's three banks.

Figure 2-10. HSMC Signal and Bank Diagram



The HSMC interface has programmable bi-directional I/O pins that can be used as 2.5-V LVCMOS, which is 3.3-V LVTTTL-compatible. These pins can also be used as various differential I/O standards including, but not limited to, LVDS, mini-LVDS, and RSDS with up to 17 full-duplex channels.



As noted in the *High Speed Mezzanine Card (HSMC) Specification* manual, LVDS and single-ended I/O standards are only guaranteed to function when mixed according to either the generic single-ended pin-out or generic differential pin-out.

Table 2–36 lists the HSMC port A interface pin assignments, signal names, and functions.

Table 2–36. HSMC Port A Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J2.17	Transceiver TX bit 3	HSMA_TX_P3	1.5-V PCML	K31
J2.18	Transceiver RX bit 3	HSMA_RX_P3		L33
J2.19	Transceiver TX bit 3n	HSMA_TX_N3		K32
J2.20	Transceiver RX bit 3n	HSMA_RX_N3		L34
J2.21	Transceiver TX bit 2	HSMA_TX_P2		M31
J2.22	Transceiver RX bit 2	HSMA_RX_P2		N33
J2.23	Transceiver TX bit 2n	HSMA_TX_N2		M32
J2.24	Transceiver RX bit 2n	HSMA_RX_N2		N34
J2.25	Transceiver TX bit 1	HSMA_TX_P1		P31
J2.26	Transceiver RX bit 1	HSMA_RX_P1		R33
J2.27	Transceiver TX bit 1n	HSMA_TX_N1		P32
J2.28	Transceiver RX bit 1n	HSMA_RX_N1		R34
J2.29	Transceiver TX bit 0	HSMA_TX_P0		T31
J2.30	Transceiver RX bit 0	HSMA_RX_P0		U33
J2.31	Transceiver TX bit 0n	HSMA_TX_N0		T32
J2.32	Transceiver RX bit 0n	HSMA_RX_N0		U34
J2.33	Management serial data	HSMA_SDA	2.5-V	R1
J2.34	Management serial clock	HSMA_SCL		T1
J2.35	JTAG clock signal	JTAG_TCK		L24
J2.36	JTAG mode select signal	JTAG_TMS		N25
J2.37	JTAG data output	JTAG_HSMA_TDO		—
J2.38	JTAG data input	JTAG_HSMA_TDI		—
J2.39	Dedicated CMOS clock out	HSMA_CLKOUT0		P10
J2.40	Dedicated CMOS clock in	HSMA_CLKIN0		AP17
J2.41	Dedicated CMOS I/O bit 0	HSMA_D0		L1
J2.42	Dedicated CMOS I/O bit 1	HSMA_D1		R6
J2.43	Dedicated CMOS I/O bit 2	HSMA_D2		K1
J2.44	Dedicated CMOS I/O bit 3	HSMA_D3		M1

Table 2-36. HSMC Port A Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J2.47	LVDS TX bit 0 or CMOS bit 4	HSMA_TX_D_P0	LVDS or 2.5-V	AA10
J2.48	LVDS RX bit 0 or CMOS bit 5	HSMA_RX_D_P0		AC5
J2.49	LVDS TX bit 0n or CMOS bit 6	HSMA_TX_D_N0		AA9
J2.50	LVDS RX bit 0n or CMOS bit 7	HSMA_RX_D_N0		AC4
J2.53	LVDS TX bit 1 or CMOS bit 8	HSMA_TX_D_P1		Y11
J2.54	LVDS RX bit 1 or CMOS bit 9	HSMA_RX_D_P1		AE4
J2.55	LVDS TX bit 1n or CMOS bit 10	HSMA_TX_D_N1		Y10
J2.56	LVDS RX bit 1n or CMOS bit 11	HSMA_RX_D_N1		AF4
J2.59	LVDS TX bit 2 or CMOS bit 12	HSMA_TX_D_P2		AH2
J2.60	LVDS RX bit 2 or CMOS bit 13	HSMA_RX_D_P2		AF1
J2.61	LVDS TX bit 2n or CMOS bit 14	HSMA_TX_D_N2		AH1
J2.62	LVDS RX bit 2n or CMOS bit 15	HSMA_RX_D_N2		AG1
J2.65	LVDS TX bit 3 or CMOS bit 16	HSMA_TX_D_P3		AB10
J2.66	LVDS RX bit 3 or CMOS bit 17	HSMA_RX_D_P3		AE2
J2.67	LVDS TX bit 3n or CMOS bit 18	HSMA_TX_D_N3		AB9
J2.68	LVDS RX bit 3n or CMOS bit 19	HSMA_RX_D_N3		AE1
J2.71	LVDS TX bit 4 or CMOS bit 20	HSMA_TX_D_P4		Y8
J2.72	LVDS RX bit 4 or CMOS bit 21	HSMA_RX_D_P4		AC1
J2.73	LVDS TX bit 4n or CMOS bit 22	HSMA_TX_D_N4		Y7
J2.74	LVDS RX bit 4n or CMOS bit 23	HSMA_RX_D_N4		AD1
J2.77	LVDS TX bit 5 or CMOS bit 24	HSMA_TX_D_P5		AF3
J2.78	LVDS RX bit 5 or CMOS bit 25	HSMA_RX_D_P5		AB2
J2.79	LVDS TX bit 5n or CMOS bit 26	HSMA_TX_D_N5		AF2
J2.80	LVDS RX bit 5n or CMOS bit 27	HSMA_RX_D_N5		AB1
J2.83	LVDS TX bit 6 or CMOS bit 28	HSMA_TX_D_P6		AD4
J2.84	LVDS RX bit 6 or CMOS bit 29	HSMA_RX_D_P6		Y1
J2.85	LVDS TX bit 6n or CMOS bit 30	HSMA_TX_D_N6		AE3
J2.86	LVDS RX bit 6n or CMOS bit 31	HSMA_RX_D_N6		AA1
J2.89	LVDS TX bit 7 or CMOS bit 32	HSMA_TX_D_P7		V4
J2.90	LVDS RX bit 7 or CMOS bit 33	HSMA_RX_D_P7		Y2
J2.91	LVDS TX bit 7n or CMOS bit 34	HSMA_TX_D_N7		V3
J2.92	LVDS RX bit 7n or CMOS bit 35	HSMA_RX_D_N7		W1
J2.95	LVDS or CMOS clock out 1 or CMOS bit 36	HSMA_CLKOUT_P1		AD7
J2.96	LVDS or CMOS clock in 1 or CMOS bit 37	HSMA_CLKIN_P1		U6
J2.97	LVDS or CMOS clock out 1 or CMOS bit 38	HSMA_CLKOUT_N1		AD6
J2.98	LVDS or CMOS clock in 1 or CMOS bit 39	HSMA_CLKIN_N1		U5
J2.101	LVDS TX bit 8 or CMOS bit 40	HSMA_TX_D_P8		AA7
J2.102	LVDS RX bit 8 or CMOS bit 41	HSMA_RX_D_P8		V2

Table 2-36. HSMC Port A Pin Assignments, Schematic Signal Names, and Functions (Part 3 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J2.103	LVDS TX bit 8n or CMOS bit 42	HSMA_TX_D_N8	LVDS or 2.5-V	Y6
J2.104	LVDS RX bit 8n or CMOS bit 43	HSMA_RX_D_N8		V1
J2.107	LVDS TX bit 9 or CMOS bit 44	HSMA_TX_D_P9		W7
J2.108	LVDS RX bit 9 or CMOS bit 45	HSMA_RX_D_P9		W4
J2.109	LVDS TX bit 9n or CMOS bit 46	HSMA_TX_D_N9		W6
J2.110	LVDS RX bit 9n or CMOS bit 47	HSMA_RX_D_N9		W3
J2.113	LVDS TX bit 10 or CMOS bit 48	HSMA_TX_D_P10		Y5
J2.114	LVDS RX bit 10 or CMOS bit 49	HSMA_RX_D_P10		U2
J2.115	LVDS TX bit 10n or CMOS bit 50	HSMA_TX_D_N10		AA4
J2.116	LVDS RX bit 10n or CMOS bit 51	HSMA_RX_D_N10		U1
J2.119	LVDS TX bit 11 or CMOS bit 52	HSMA_TX_D_P11		AC3
J2.120	LVDS RX bit 11 or CMOS bit 53	HSMA_RX_D_P11		Y4
J2.121	LVDS TX bit 11n or CMOS bit 54	HSMA_TX_D_N11		AC2
J2.122	LVDS RX bit 11n or CMOS bit 55	HSMA_RX_D_N11		Y3
J2.125	LVDS TX bit 12 or CMOS bit 56	HSMA_TX_D_P12		W10
J2.126	LVDS RX bit 12 or CMOS bit 57	HSMA_RX_D_P12		AB4
J2.127	LVDS TX bit 12n or CMOS bit 58	HSMA_TX_D_N12		Y9
J2.128	LVDS RX bit 12n or CMOS bit 59	HSMA_RX_D_N12		AB3
J2.131	LVDS TX bit 13 or CMOS bit 60	HSMA_TX_D_P13		R7
J2.132	LVDS RX bit 13 or CMOS bit 61	HSMA_RX_D_P13		AB6
J2.133	LVDS TX bit 13n or CMOS bit 62	HSMA_TX_D_N13		T7
J2.134	LVDS RX bit 13n or CMOS bit 63	HSMA_RX_D_N13		AB5
J2.137	LVDS TX bit 14 or CMOS bit 64	HSMA_TX_D_P14		R2
J2.138	LVDS RX bit 14 or CMOS bit 65	HSMA_RX_D_P14		U7
J2.139	LVDS TX bit 14n or CMOS bit 66	HSMA_TX_D_N14		P1
J2.140	LVDS RX bit 14n or CMOS bit 67	HSMA_RX_D_N14		V7
J2.143	LVDS TX bit 15 or CMOS bit 68	HSMA_TX_D_P15		V11
J2.144	LVDS RX bit 15 or CMOS bit 69	HSMA_RX_D_P15		AB8
J2.145	LVDS TX bit 15n or CMOS bit 70	HSMA_TX_D_N15		V10
J2.146	LVDS RX bit 15n or CMOS bit 71	HSMA_RX_D_N15		AB7
J2.149	LVDS TX bit 16 or CMOS bit 72	HSMA_TX_D_P16		U11
J2.150	LVDS RX bit 16 or CMOS bit 73	HSMA_RX_D_P16		AC7
J2.151	LVDS TX bit 16n or CMOS bit 74	HSMA_TX_D_N16		U10
J2.152	LVDS RX bit 16n or CMOS bit 75	HSMA_RX_D_N16		AC6
J2.155	LVDS or CMOS clock out 2 or CMOS bit 76	HSMA_CLKOUT_P2		V12
J2.156	LVDS or CMOS clock in 2 or CMOS bit 77	HSMA_CLKIN_P2		K18
J2.157	LVDS or CMOS clock out 2 or CMOS bit 78	HSMA_CLKOUT_N2		W12
J2.158	LVDS or CMOS clock in 2 or CMOS bit 79	HSMA_CLKIN_N2		J18

Table 2-36. HSMC Port A Pin Assignments, Schematic Signal Names, and Functions (Part 4 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J2.160	HSMC port A presence detect	HSMA_PSNT_n	2.5-V	U3
D4	User LED to show RX data activity on HSMC port A	HSMA_RX_LED		N5
D5	User LED to show TX data activity on HSMC port A	HSMA_TX_LED		C29

Table 2-37 lists the HSMC port B interface pin assignments, signal names, and functions.

Table 2-37. HSMC Port B Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J1.17	Transceiver TX bit 3	HSMB_TX_P3	1.5-V PCML	B31
J1.18	Transceiver RX bit 3	HSMB_RX_P3		C33
J1.19	Transceiver TX bit 3n	HSMB_TX_N3		B32
J1.20	Transceiver RX bit 3n	HSMB_RX_N3		C34
J1.21	Transceiver TX bit 2	HSMB_TX_P2		D31
J1.22	Transceiver RX bit 2	HSMB_RX_P2		E33
J1.23	Transceiver TX bit 2n	HSMB_TX_N2		D32
J1.24	Transceiver RX bit 2n	HSMB_RX_N2		E34
J1.25	Transceiver TX bit 1	HSMB_TX_P1		F31
J1.26	Transceiver RX bit 1	HSMB_RX_P1		G33
J1.27	Transceiver TX bit 1n	HSMB_TX_N1		F32
J1.28	Transceiver RX bit 1n	HSMB_RX_N1		G34
J1.29	Transceiver TX bit 0	HSMB_TX_P0		H31
J1.30	Transceiver RX bit 0	HSMB_RX_P0		J33
J1.31	Transceiver TX bit 0n	HSMB_TX_N0		H32
J1.32	Transceiver RX bit 0n	HSMB_RX_N0		J34
J1.33	Management serial data	HSMB_SDA	2.5-V	AK27
J1.34	Management serial clock	HSMB_SCL		AJ27
J1.35	JTAG clock signal	JTAG_TCK		L24
J1.36	JTAG mode select signal	JTAG_TMS		N25
J1.37	JTAG data output	JTAG_HSMB_TDO		—
J1.38	JTAG data input	JTAG_HSMB_TDI		—
J1.39	Dedicated CMOS clock out	HSMB_CLKOUT0		AG30
J1.40	Dedicated CMOS clock in	HSMB_CLKIN0		AP16
J1.41	Dedicated CMOS I/O bit 0	HSMB_D0		AH29
J1.42	Dedicated CMOS I/O bit 1	HSMB_D1		AH30
J1.43	Dedicated CMOS I/O bit 2	HSMB_D2		AK30

Table 2-37. HSMC Port B Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J1.44	Dedicated CMOS I/O bit 3	HSMB_D3	2.5-V	AJ30
J1.47	Dedicated CMOS I/O bit 4	HSMB_D4		AF28
J1.48	Dedicated CMOS I/O bit 5	HSMB_D5		AJ29
J1.49	Dedicated CMOS I/O bit 6	HSMB_D6		AL28
J1.50	Dedicated CMOS I/O bit 7	HSMB_D7		AE28
J1.53	Dedicated CMOS I/O bit 8	HSMB_D8		AK28
J1.54	Dedicated CMOS I/O bit 9	HSMB_D9		AH28
J1.55	Dedicated CMOS I/O bit 10	HSMB_D10		AJ28
J1.56	Dedicated CMOS I/O bit 11	HSMB_D11		AH27
J1.59	Dedicated CMOS I/O bit 12	HSMB_D12		AJ26
J1.60	Dedicated CMOS I/O bit 13	HSMB_D13	LVDS or 2.5-V	AG27
J1.61	Dedicated CMOS I/O bit 14	HSMB_D14		AH26
J1.62	Dedicated CMOS I/O bit 15	HSMB_D15		AF27
J1.65	Dedicated CMOS I/O bit 16	HSMB_D16		AG24
J1.66	Dedicated CMOS I/O bit 17	HSMB_D17		AF24
J1.67	Dedicated CMOS I/O bit 18	HSMB_D18		AF25
J1.68	Dedicated CMOS I/O bit 19	HSMB_D19		AE23
J1.71	Dedicated CMOS I/O bit 20	HSMB_D20		AE27
J1.72	Dedicated CMOS I/O bit 21	HSMB_D21		AE21
J1.73	Dedicated CMOS I/O bit 22	HSMB_D22		AE26
J1.74	Dedicated CMOS I/O bit 23	HSMB_D23		AD21
J1.77	Dedicated CMOS I/O bit 24	HSMB_D24		AD22
J1.78	Dedicated CMOS I/O bit 25	HSMB_D25		AC22
J1.79	Dedicated CMOS I/O bit 26	HSMB_D26		AG4
J1.80	Dedicated CMOS I/O bit 27	HSMB_D27		AH5
J1.83	Dedicated CMOS I/O bit 28	HSMB_D28		AF6
J1.84	Dedicated CMOS I/O bit 29	HSMB_D29		AF5
J1.85	Dedicated CMOS I/O bit 30	HSMB_D30		AH7
J1.86	Dedicated CMOS I/O bit 31	HSMB_D31		AG6
J1.89	Dedicated CMOS I/O bit 32	HSMB_D32		AG7
J1.90	Dedicated CMOS I/O bit 33	HSMB_D33		AF7
J1.91	Dedicated CMOS I/O bit 34	HSMB_D34		AE7
J1.92	Dedicated CMOS I/O bit 35	HSMB_D35		AE8
J1.95	Dedicated CMOS I/O bit 36	HSMB_D36		AF8
J1.96	Dedicated CMOS I/O bit 37	HSMB_D37		AD10
J1.97	Dedicated CMOS I/O bit 38	HSMB_D38		AD9
J1.98	Dedicated CMOS I/O bit 39	HSMB_D39		AJ6
J1.101	Dedicated CMOS I/O bit 40	HSMB_D40		AK4

Table 2-37. HSMC Port B Pin Assignments, Schematic Signal Names, and Functions (Part 3 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J1.102	Dedicated CMOS I/O bit 41	HSMB_D41	LVDS or 2.5-V	AL2
J1.103	Dedicated CMOS I/O bit 42	HSMB_D42		AK3
J1.104	Dedicated CMOS I/O bit 43	HSMB_D43		AL1
J1.107	Dedicated CMOS I/O bit 44	HSMB_D44		AJ4
J1.108	Dedicated CMOS I/O bit 45	HSMB_D45		AK1
J1.109	Dedicated CMOS I/O bit 46	HSMB_D46		AJ3
J1.110	Dedicated CMOS I/O bit 47	HSMB_D47		AJ1
J1.113	Dedicated CMOS I/O bit 48	HSMB_D48		AJ2
J1.114	Dedicated CMOS I/O bit 49	HSMB_D49		AH3
J1.115	Dedicated CMOS I/O bit 50	HSMB_D50		AH6
J1.116	Dedicated CMOS I/O bit 51	HSMB_D51	2.5-V	AH4
J1.119	Dedicated CMOS I/O bit 52	HSMB_D52		AC10
J1.120	Dedicated CMOS I/O bit 53	HSMB_D53		M10
J1.121	Dedicated CMOS I/O bit 54	HSMB_D54		AC11
J1.122	Dedicated CMOS I/O bit 55	HSMB_D55		M9
J1.125	Dedicated CMOS I/O bit 56	HSMB_D56		M8
J1.126	Dedicated CMOS I/O bit 57	HSMB_D57		L7
J1.127	Dedicated CMOS I/O bit 58	HSMB_D58		M7
J1.128	Dedicated CMOS I/O bit 59	HSMB_D59		K8
J1.131	Dedicated CMOS I/O bit 60	HSMB_D60		K7
J1.132	Dedicated CMOS I/O bit 61	HSMB_D61		J8
J1.133	Dedicated CMOS I/O bit 62	HSMB_D62		K6
J1.134	Dedicated CMOS I/O bit 63	HSMB_D63		J6
J1.137	Dedicated CMOS I/O bit 64	HSMB_D64		J7
J1.138	Dedicated CMOS I/O bit 65	HSMB_D65		G5
J1.139	Dedicated CMOS I/O bit 66	HSMB_D66		H7
J1.140	Dedicated CMOS I/O bit 67	HSMB_D67		F5
J1.143	Dedicated CMOS I/O bit 68	HSMB_D68		G6
J1.144	Dedicated CMOS I/O bit 69	HSMB_D69		D5
J1.145	Dedicated CMOS I/O bit 70	HSMB_D70		G4
J1.146	Dedicated CMOS I/O bit 71	HSMB_D71		C6
J1.149	Dedicated CMOS I/O bit 72	HSMB_D72		D6
J1.150	Dedicated CMOS I/O bit 73	HSMB_D73		C5
J1.151	—	—		—
J1.152	—	—		—
J1.155	LVDS or CMOS clock out 2 or CMOS bit 76	HSMB_CLKOUT_P2		N8
J1.156	Dedicated CMOS I/O bit 74	HSMB_D74		AE5
J1.157	LVDS or CMOS clock out 2 or CMOS bit 77	HSMB_CLKOUT_N2		N7

Table 2-37. HSMC Port B Pin Assignments, Schematic Signal Names, and Functions (Part 4 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J1.158	Dedicated CMOS I/O bit 75	HSMB_D75	2.5-V	V5
J1.160	HSMC port B presence detect	HSMB_PSNT_n		AG28
D2	User LED to show RX data activity on HSMC port B	HSMB_RX_LED		AF23
D3	User LED to show TX data activity on HSMC port B	HSMB_TX_LED		AE24

Table 2-38 lists the HSMC connector component reference and manufacturing information.

Table 2-38. HSMC Connector Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
J1 and J2	HSMC, custom version of QSH-DP family high-speed socket.	Samtec	ASP-122953-01	www.samtec.com

Memory

This section describes the board's memory interface support and also their signal names, types, and connectivity relative to the Arria II GX device. The board has the following memory interfaces:

- DDR3
- DDR2 SODIMM
- SSRAM
- Flash



For more information about the memory interfaces, refer to the following documents:

- *Timing Analysis* section in volume 4 of the External Memory Interface Handbook.
- *DDR, DDR2, and DDR3 SDRAM Design Tutorials* section in volume 6 of the External Memory Interface Handbook.

DDR3

There is a single DDR3 device, providing 128-Mbyte interface with a 16-bit data bus. This memory interface is designed to run at a maximum frequency of 333 MHz for a maximum theoretical bandwidth of over 10.6 Gbps. The internal bus in the FPGA is typically 2 or 4 times the width at full-rate or half-rate respectively. For example, a 333 MHz 16-bit interface will become a 166.5 MHz 64-bit bus.

Table 2-39 lists the DDR3 pin assignments, signal names, and functions. The signal names and types are relative to the Arria II device in terms of I/O setting and direction.

Table 2-39. DDR3 Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U13.N3	Address bus	DDR3_A0	1.5-V SSTL Class I	G16
U13.P7	Address bus	DDR3_A1		A12
U13.P3	Address bus	DDR3_A2		H18
U13.N2	Address bus	DDR3_A3		F16
U13.P8	Address bus	DDR3_A4		A7
U13.P2	Address bus	DDR3_A5		G17
U13.R8	Address bus	DDR3_A6		C13
U13.R2	Address bus	DDR3_A7		K14
U13.T8	Address bus	DDR3_A8		D11
U13.R3	Address bus	DDR3_A9		M16
U13.L7	Address bus	DDR3_A10		A11
U13.R7	Address bus	DDR3_A11		E15
U13.N7	Address bus	DDR3_A12		A8
U13.T3	Address bus	DDR3_A13		M17
U13.T7	Address bus	DDR3_A14		B15
U13.M2	Bank address bus	DDR3_BA0		D16
U13.N8	Bank address bus	DDR3_BA1		C12
U13.M3	Bank address bus	DDR3_BA2		C16
U13.K3	Column address select	DDR3_CAS_n		D15
U13.K9	Clock enable	DDR3_CKE		B10
U13.L2	Chip select	DDR3_CS_n		A10
U13.K1	Termination enable	DDR3_ODT		E16
U13.J3	Row address select	DDR3_RAS_n		A13
U13.T2	Reset	DDR3_RST_n		G18
U13.L3	Write enable	DDR3_WE_n		A15
U13.J7	Clock P	DDR3_CLK_P	Differential 1.5-V SSTL Class I	B13
U13.K7	Clock N	DDR3_CLK_N		B12

Table 2–39. DDR3 Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U13.E3	Data bus byte lane 0	DDR3_DQ0	1.5-V SSTL Class I	J16
U13.F7	Data bus byte lane 0	DDR3_DQ1		B7
U13.F2	Data bus byte lane 0	DDR3_DQ2		K17
U13.F8	Data bus byte lane 0	DDR3_DQ3		A6
U13.H3	Data bus byte lane 0	DDR3_DQ4		A3
U13.H8	Data bus byte lane 0	DDR3_DQ5		A4
U13.G2	Data bus byte lane 0	DDR3_DQ6		L16
U13.H7	Data bus byte lane 0	DDR3_DQ7		B3
U13.E7	Write mask byte lane 0	DDR3_DM0		B9
U13.F3	Data strobe P byte lane 0	DDR3_QS_P0		G14
U13.G3	Data strobe N byte lane 0	DDR3_QS_N0		F15
U13.D7	Data bus byte lane 1	DDR3_DQ8		D13
U13.C3	Data bus byte lane 1	DDR3_DQ9		F13
U13.C8	Data bus byte lane 1	DDR3_DQ10		A2
U13.C2	Data bus byte lane 1	DDR3_DQ11		J15
U13.A7	Data bus byte lane 1	DDR3_DQ12		D12
U13.A2	Data bus byte lane 1	DDR3_DQ13		G15
U13.B8	Data bus byte lane 1	DDR3_DQ14		B4
U13.A3	Data bus byte lane 1	DDR3_DQ15		G13
U13.D3	Write mask byte lane 1	DDR3_DM1		K15
U13.C7	Data strobe P byte lane 1	DDR3_QS_P1		F12
U13.B7	Data strobe N byte lane 1	DDR3_QS_N1		E12

Table 2–40 lists the DDR3 component reference and manufacturing information.

Table 2–40. DDR3 Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U13	8 M × 16 × 8 banks, 667M, CL9	Micron	MT41J64M16LA-15E	www.micron.com

DDR2 SODIMM

There is a DDR2 200-pin SODIMM device, providing 1-Gbyte single-rank DIMM with a 64-bit data bus. This memory interface is designed to run at a maximum frequency of 333 MHz for a maximum theoretical bandwidth of over 42.6 Gbps. The internal bus in the FPGA is typically 2 or 4 times the width at full rate or half rate respectively. For example, a 333 MHz 64-bit interface will become a 166.5 MHz 256-bit bus.

Table 2–41 lists the DDR2 SODIMM pin assignments, signal names, and its functions. The signal names and types are relative to the Arria II device in terms of I/O setting and direction.

Table 2-41. DDR2 SODIMM Pin Assignments, Signal Names and Functions (Part 1 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J7.102	Address bus	DDR2_A0	1.8-V SSTL Class I	AH14
J7.101	Address bus	DDR2_A1		AK12
J7.100	Address bus	DDR2_A2		AE12
J7.99	Address bus	DDR2_A3		AH13
J7.98	Address bus	DDR2_A4		AF14
J7.97	Address bus	DDR2_A5		AG12
J7.94	Address bus	DDR2_A6		AJ18
J7.92	Address bus	DDR2_A7		AL19
J7.93	Address bus	DDR2_A8		AG13
J7.91	Address bus	DDR2_A9		AE13
J7.105	Address bus	DDR2_A10		AK10
J7.90	Address bus	DDR2_A11		AH23
J7.89	Address bus	DDR2_A12		AF13
J7.116	Address bus	DDR2_A13		AM5
J7.86	Address bus	DDR2_A14		AH24
J7.84	Address bus	DDR2_A15		AP28
J7.107	Bank address bus	DDR2_BA0		AJ11
J7.106	Bank address bus	DDR2_BA1		AJ13
J7.85	Bank address bus	DDR2_BA2		AE14
J7.113	Column address select	DDR2_CAS_n		AL8
J7.79	Clock enable	DDR2_CKE0		AP8
J7.110	Chip select rank 0	DDR2_CS_n0		AM13
J7.115	Chip select rank 1	DDR2_CS_n1		AL9
J7.114	Termination enable rank 0	DDR2_ODT0		AJ10
J7.119	Termination enable rank 1	DDR2_ODT1		AF12
J7.108	Row address select	DDR2_RAS_n		AH12
J7.197	EEPROM serial clock	DDR2_SCL		—
J7.195	EEPROM serial data	DDR2_SDA		—
J7.109	Write enable	DDR2_WE_n		AM6
J7.30	Clock P0	DDR2_CLK_P0	Differential 1.8-V SSTL Class I	AJ7
J7.32	Clock N0	DDR2_CLK_N0		AK7
J7.164	Clock P1	DDR2_CLK_P1		AK6
J7.166	Clock N1	DDR2_CLK_N1		AL6

Table 2-41. DDR2 SODIMM Pin Assignments, Signal Names and Functions (Part 2 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J7.5	Data bus byte lane 0	DDR2_DQ0	1.8-V SSTL Class I	AG21
J7.7	Data bus byte lane 0	DDR2_DQ1		AL29
J7.17	Data bus byte lane 0	DDR2_DQ2		AM29
J7.19	Data bus byte lane 0	DDR2_DQ3		AM28
J7.4	Data bus byte lane 0	DDR2_DQ4		AP29
J7.6	Data bus byte lane 0	DDR2_DQ5		AN28
J7.14	Data bus byte lane 0	DDR2_DQ6		AJ24
J7.16	Data bus byte lane 0	DDR2_DQ7		AJ25
J7.10	Write mask byte lane 0	DDR2_DM0		AK22
J7.13	Data strobe P byte lane 0	DDR2_QS0		AM25
J7.11	Data strobe N byte lane 0	DDR2_QSN0		AM26
J7.23	Data bus byte lane 1	DDR2_DQ8		AP27
J7.25	Data bus byte lane 1	DDR2_DQ9		AM24
J7.35	Data bus byte lane 1	DDR2_DQ10		AM23
J7.37	Data bus byte lane 1	DDR2_DQ11		AP25
J7.20	Data bus byte lane 1	DDR2_DQ12		AJ23
J7.22	Data bus byte lane 1	DDR2_DQ13		AL24
J7.36	Data bus byte lane 1	DDR2_DQ14		AG22
J7.38	Data bus byte lane 1	DDR2_DQ15		AH21
J7.26	Write mask byte lane 1	DDR2_DM1		AE19
J7.31	Data strobe P byte lane 1	DDR2_QS1		AN24
J7.29	Data strobe N byte lane 1	DDR2_QSN1		AP24
J7.43	Data bus byte lane 2	DDR2_DQ16		AL25
J7.45	Data bus byte lane 2	DDR2_DQ17		AK25
J7.55	Data bus byte lane 2	DDR2_DQ18		AP23
J7.57	Data bus byte lane 2	DDR2_DQ19		AM22
J7.44	Data bus byte lane 2	DDR2_DQ20		AL21
J7.46	Data bus byte lane 2	DDR2_DQ21		AL20
J7.56	Data bus byte lane 2	DDR2_DQ22		AJ21
J7.58	Data bus byte lane 2	DDR2_DQ23		AH20
J7.52	Write mask byte lane 2	DDR2_DM2		AG19
J7.51	Data strobe P byte lane 2	DDR2_QS2		AP21
J7.49	Data strobe N byte lane 2	DDR2_QSN2		AP22
J7.61	Data bus byte lane 3	DDR2_DQ24		AN21
J7.63	Data bus byte lane 3	DDR2_DQ25		AM21
J7.73	Data bus byte lane 3	DDR2_DQ26		AE18
J7.75	Data bus byte lane 3	DDR2_DQ27		AP18
J7.62	Data bus byte lane 3	DDR2_DQ28		AH19

Table 2-41. DDR2 SODIMM Pin Assignments, Signal Names and Functions (Part 3 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J7.64	Data bus byte lane 3	DDR2_DQ29	1.8-V SSTL Class I	AN19
J7.74	Data bus byte lane 3	DDR2_DQ30		AK18
J7.76	Data bus byte lane 3	DDR2_DQ31		AF18
J7.67	Write mask byte lane 3	DDR2_DM3		AP20
J7.70	Data strobe P byte lane 3	DDR2_DQS3		AL18
J7.68	Data strobe N byte lane 3	DDR2_DQSN3		AM18
J7.123	Data bus byte lane 4	DDR2_DQ32		AP15
J7.125	Data bus byte lane 4	DDR2_DQ33		AN15
J7.135	Data bus byte lane 4	DDR2_DQ34		AH17
J7.137	Data bus byte lane 4	DDR2_DQ35		AF17
J7.124	Data bus byte lane 4	DDR2_DQ36		AC18
J7.126	Data bus byte lane 4	DDR2_DQ37		AE17
J7.134	Data bus byte lane 4	DDR2_DQ38		AP14
J7.136	Data bus byte lane 4	DDR2_DQ39		AN13
J7.130	Write mask byte lane 4	DDR2_DM4		AH18
J7.131	Data strobe P byte lane 4	DDR2_DQS4		AM16
J7.129	Data strobe N byte lane 4	DDR2_DQSN4		AM17
J7.141	Data bus byte lane 5	DDR2_DQ40		AH16
J7.143	Data bus byte lane 5	DDR2_DQ41		AH15
J7.151	Data bus byte lane 5	DDR2_DQ42		AP10
J7.153	Data bus byte lane 5	DDR2_DQ43		AP9
J7.140	Data bus byte lane 5	DDR2_DQ44		AL16
J7.142	Data bus byte lane 5	DDR2_DQ45		AK16
J7.152	Data bus byte lane 5	DDR2_DQ46		AP12
J7.154	Data bus byte lane 5	DDR2_DQ47		AN12
J7.147	Write mask byte lane 5	DDR2_DM5		AG16
J7.148	Data strobe P byte lane 5	DDR2_DQS5		AK15
J7.146	Data strobe N byte lane 5	DDR2_DQSN5		AL15
J7.157	Data bus byte lane 6	DDR2_DQ48		AN7
J7.159	Data bus byte lane 6	DDR2_DQ49		AP7
J7.173	Data bus byte lane 6	DDR2_DQ50		AP6
J7.175	Data bus byte lane 6	DDR2_DQ51		AP5
J7.158	Data bus byte lane 6	DDR2_DQ52		AF16
J7.160	Data bus byte lane 6	DDR2_DQ53		AL14
J7.174	Data bus byte lane 6	DDR2_DQ54		AE16
J7.176	Data bus byte lane 6	DDR2_DQ55		AL11
J7.170	Write mask byte lane 6	DDR2_DM6		AC15
J7.169	Data strobe P byte lane 6	DDR2_DQS6		AK13

Table 2-41. DDR2 SODIMM Pin Assignments, Signal Names and Functions (Part 4 of 4)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
J7.167	Data strobe N byte lane 6	DDR2_DQSN6	1.8-V SSTL Class I	AL12
J7.179	Data bus byte lane 7	DDR2_DQ56		AM10
J7.181	Data bus byte lane 7	DDR2_DQ57		AF15
J7.189	Data bus byte lane 7	DDR2_DQ58		AP2
J7.191	Data bus byte lane 7	DDR2_DQ59		AJ12
J7.180	Data bus byte lane 7	DDR2_DQ60		AJ16
J7.182	Data bus byte lane 7	DDR2_DQ61		AN9
J7.192	Data bus byte lane 7	DDR2_DQ62		AP3
J7.194	Data bus byte lane 7	DDR2_DQ63		AN4
J7.185	Write mask byte lane 7	DDR2_DM7		AE15
J7.188	Data strobe P byte lane 7	DDR2_DQS7		AM7
J7.186	Data strobe N byte lane 7	DDR2_DQSN7		AM8

Table 2-42 lists the DDR2 SODIMM component references and manufacturing information.

Table 2-42. DDR2 SODIMM Component References and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
J7	200-pin DDR2 SODIMM socket	Tyco Electronics	1-1734075-1	www.tycoelectronics.com
Module	128 M × 8 banks, 400M, CL6	Micron	MT8HTF12864HZ-800G1	www.micron.com

SSRAM

The SSRAM device consists of a single standard synchronous SRAM, providing 2 Mbyte of with a 36-bit data bus. This device is part of the shared FSM bus which connects to the flash memory, SRAM, and MAX II CPLD EPM2210 System Controller.

The device speed is 200 MHz single-data-rate. There is no minimum speed for this device. The theoretical bandwidth of this 32-bit memory interface is 6.4 Gbps for continuous bursts. The read latency for any address is two clocks, in which at 200 MHz, the latency is 10 ns and at 50 MHz, the latency is 40 ns. The write latency is one clock.

Table 2-43 lists the SSRAM pin assignments, signal names, and functions. The signal names and types are relative to the Arria II GX device in terms of I/O setting and direction.

Table 2-43. SSRAM Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U22.R6	Address bus	FSM_A2	2.5-V	D29
U22.P6	Address bus	FSM_A3		J21
U22.A2	Address bus	FSM_A4		L13
U22.A10	Address bus	FSM_A5		C8
U22.B2	Address bus	FSM_A6		N9
U22.B10	Address bus	FSM_A7		D20
U22.N6	Address bus	FSM_A8		A23
U22.P3	Address bus	FSM_A9		B24
U22.P4	Address bus	FSM_A10		C24
U22.P8	Address bus	FSM_A11		E25
U22.P9	Address bus	FSM_A12		F21
U22.P10	Address bus	FSM_A13		J19
U22.P11	Address bus	FSM_A14		H19
U22.R3	Address bus	FSM_A15		K21
U22.R4	Address bus	FSM_A16		L21
U22.R8	Address bus	FSM_A17		F25
U22.R9	Address bus	FSM_A18		F26
U22.R10	Address bus	FSM_A19		G23
U22.R11	Address bus	FSM_A20		H21
U22.B1	Address bus	FSM_A21		M13
U22.A1	Address bus	FSM_A22		P7
U22.J10	Data bus	FSM_D0		A19
U22.J11	Data bus	FSM_D1		C18
U22.K10	Data bus	FSM_D2		D28
U22.K11	Data bus	FSM_D3		B19
U22.L10	Data bus	FSM_D4		E19
U22.L11	Data bus	FSM_D5		E18
U22.M10	Data bus	FSM_D6		G19
U22.M11	Data bus	FSM_D7		F19
U22.D10	Data bus	FSM_D8		D21
U22.D11	Data bus	FSM_D9		D23
U22.E10	Data bus	FSM_D10		D24
U22.E11	Data bus	FSM_D11		A25
U22.F10	Data bus	FSM_D12		B25
U22.F11	Data bus	FSM_D13		A26
U22.G10	Data bus	FSM_D14		C26
U22.G11	Data bus	FSM_D15		A27
U22.D1	Data bus	FSM_D16		R9

Table 2-43. SSRAM Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U22.D2	Data bus	FSM_D17	2.5-V	R10
U22.E1	Data bus	FSM_D18		R8
U22.E2	Data bus	FSM_D19		A17
U22.F1	Data bus	FSM_D20		D22
U22.F2	Data bus	FSM_D21		T10
U22.G1	Data bus	FSM_D22		P4
U22.G2	Data bus	FSM_D23		R11
U22.J1	Data bus	FSM_D24		A18
U22.J2	Data bus	FSM_D25		B18
U22.K1	Data bus	FSM_D26		C19
U22.K2	Data bus	FSM_D27		D19
U22.L1	Data bus	FSM_D28		B21
U22.L2	Data bus	FSM_D29		A21
U22.M1	Data bus	FSM_D30		C21
U22.M2	Data bus	FSM_D31		A22
U22.A8	Address status controller	SRAM_ADSCn		C10
U22.B9	Address status processor	SRAM_ADSPn		A20
U22.A9	Address valid	SRAM_ADVn		D9
U22.A7	Byte write enable	SRAM_WEn		J11
U22.B5	Byte lane 0 write enable	SRAM_BEN0		J13
U22.A5	Byte lane 1 write enable	SRAM_BEN1		H12
U22.A4	Byte lane 2 write enable	SRAM_BEN2		E9
U22.B4	Byte lane 3 write enable	SRAM_BEN3		H13
U22.A3	Chip enable	SRAM_CE1n		E10
U22.B6	Clock	SRAM_CLK		J12
U22.N11	Data bus parity byte lane 0	SRAM_DQP0		A24
U22.C11	Data bus parity byte lane 1	SRAM_DQP1		B22
U22.C1	Data bus parity byte lane 2	SRAM_DQP2		P9
U22.N1	Data bus parity byte lane 3	SRAM_DQP3		G22
U22.B7	Global write enable	SRAM_GWn		K12
U22.R1	Mode	SRAM_MODE		— (Connects to the MAX II CPLD EPM2210 System Controller)
U22.B8	Output enable	SRAM_OEn		D10
U22.H11	Sleep	SRAM_ZZ		B27

Table 2-44 lists the SSRAM component reference and manufacturing information.

Table 2-44. SSRAM Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U22	Standard Synchronous Pipelined SCD, 512K × 36, 200 MHz	ISSI Inc.	IS61VPS51236A-200B3	www.issi.com

Flash

The flash interface consists of a single synchronous flash memory device, providing 64 Mbyte with a 16-bit data bus. This device is part of the shared FSM bus which connects to the flash memory, SRAM, and MAX II CPLD EPM2210 System Controller.

There are two 512-Mbyte die per package. The parameter blocks are 32 K and main blocks are 128 K. The parameters of this device are located at the top of the address space.

This 16-bit data memory interface can sustain burst read operations at up to 52 MHz for a throughput of 832 Mbps. The write performance is 270 μs for a single word and 310 μs for a 32-word buffer. The erase time is 800 ms for a 128 K main block.

Table 2-45 lists the flash pin assignments, signal names, and functions. The signal names and types are relative to the Arria II GX device in terms of I/O setting and direction.

Table 2-45. Flash Pin Assignments, Schematic Signal Names, and Functions (Part 1 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U23.A1	Address bus	FSM_A1	2.5-V	J3
U23.B1	Address bus	FSM_A2		D29
U23.C1	Address bus	FSM_A3		J21
U23.D1	Address bus	FSM_A4		L13
U23.D2	Address bus	FSM_A5		C8
U23.A2	Address bus	FSM_A6		N9
U23.C2	Address bus	FSM_A7		D20
U23.A3	Address bus	FSM_A8		A23
U23.B3	Address bus	FSM_A9		B24
U23.C3	Address bus	FSM_A10		C24
U23.D3	Address bus	FSM_A11		E25
U23.C4	Address bus	FSM_A12		F21
U23.A5	Address bus	FSM_A13		J19
U23.B5	Address bus	FSM_A14		H19
U23.C5	Address bus	FSM_A15		K21
U23.D7	Address bus	FSM_A16		L21
U23.D8	Address bus	FSM_A17		F25

Table 2-45. Flash Pin Assignments, Schematic Signal Names, and Functions (Part 2 of 2)

Board Reference	Description	Schematic Signal Name	I/O Standard	Arria II GX Device Pin Number
U23.A7	Address bus	FSM_A18	2.5-V	F26
U23.B7	Address bus	FSM_A19		G23
U23.C7	Address bus	FSM_A20		H21
U23.C8	Address bus	FSM_A21		M13
U23.A8	Address bus	FSM_A22		P7
U23.G1	Address bus	FSM_A23		F10
U23.H8	Address bus	FSM_A24		R4
U23.B6	Address bus (die select)	FSM_A25		K4
U23.F2	Data bus	FSM_D0		A19
U23.E2	Data bus	FSM_D1		C18
U23.G3	Data bus	FSM_D2		D28
U23.E4	Data bus	FSM_D3		B19
U23.E5	Data bus	FSM_D4		E19
U23.G5	Data bus	FSM_D5		E18
U23.G6	Data bus	FSM_D6		G19
U23.H7	Data bus	FSM_D7		F19
U23.E1	Data bus	FSM_D8		D21
U23.E3	Data bus	FSM_D9		D23
U23.F3	Data bus	FSM_D10		D24
U23.F4	Data bus	FSM_D11		A25
U23.F5	Data bus	FSM_D12		B25
U23.H5	Data bus	FSM_D13		A26
U23.G7	Data bus	FSM_D14		C26
U23.E7	Data bus	FSM_D15		A27
U23.F6	Address valid	FLASH_ADVn		T4
U23.B4	Chip enable	FLASH_CEn		M3
U23.E6	Clock	FLASH_CLK		N4
U23.F8	Output enable	FLASH_OEn		K5
U23.F7	Ready	FLASH_RDYBSYn		R3
U23.D4	Reset	FLASH_RESETn		N3
U23.G8	Write enable	FLASH_WEn		C7

Table 2-46 lists the flash component reference and manufacturing information.

Table 2-46. Flash Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U23	512 Mbyte Synchronous Flash	Numonyx	PC28F512P30BF	www.numonyx.com

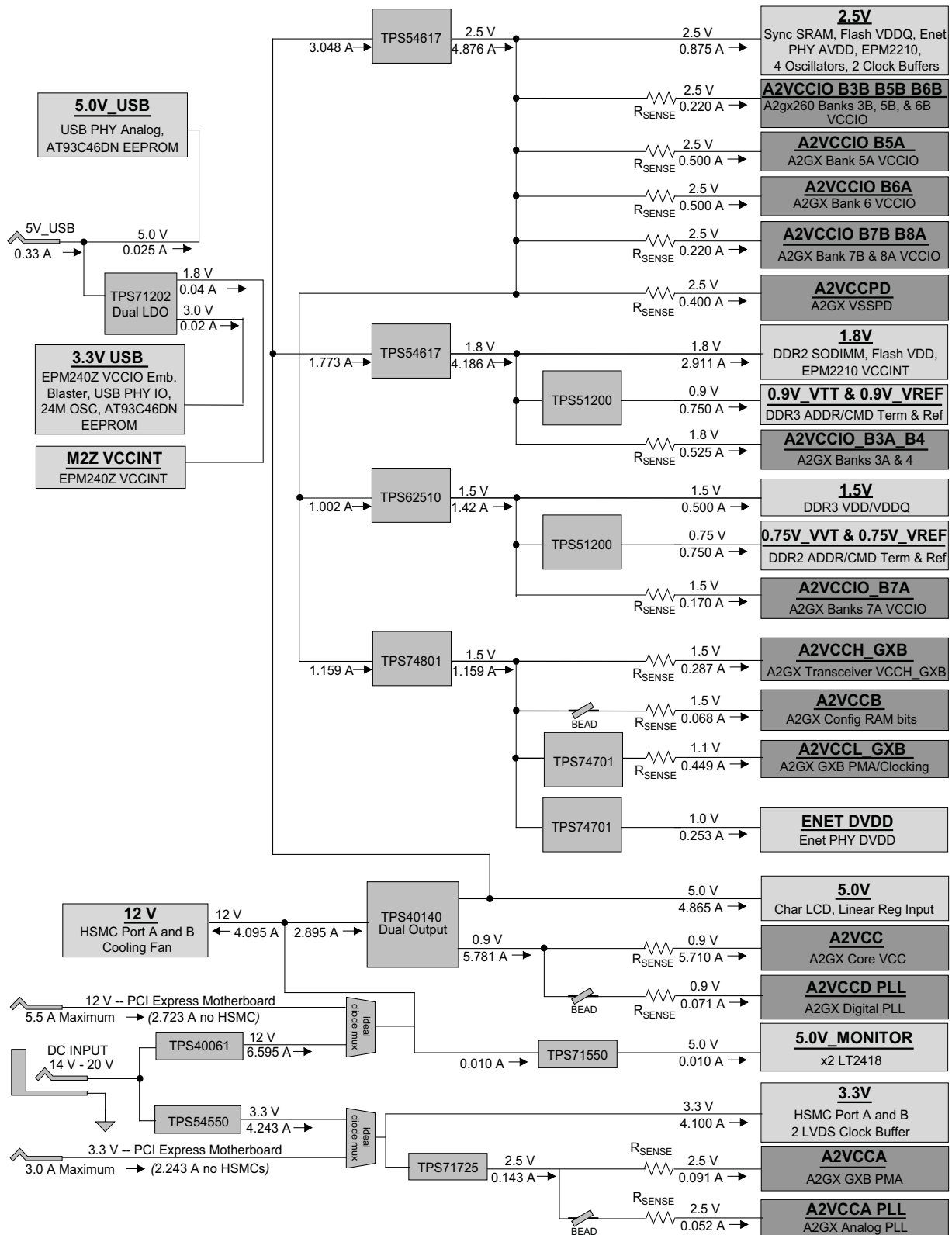
Power Supply

The development board's power is provided through a laptop style DC power input. The input voltage must be in the range of 14 V to 20 V. The DC voltage is then stepped down to various power rails used by the components on the board and installed into the HSMC connectors.

An on-board multi-channel analog-to-digital converter (ADC) is used to measure both the voltage and current for several specific board rails. The power utilization is displayed using a GUI that can graph power consumption versus time.

Power Distribution System

Figure 2-11 shows the power distribution system on the development board. Regulator inefficiencies and sharing are reflected in the currents shown, which are conservative absolute maximum levels.

Figure 2–11. Power Distribution System

Power Measurement

There are 14 power supply rails which have on-board voltage and current sense capabilities. These 8-channel differential 24-bit ADC devices and rails are split from the primary supply plane by a low-value sense resistor for the ADC to measure voltage and current. An SPI bus connects these ADC devices to the MAX II CPLD EPM2210 System Controller as well as the Arria II GX FPGA.

Figure 2-12 shows the block diagram for the power measurement circuitry.

Figure 2-12. Power Measurement Circuit

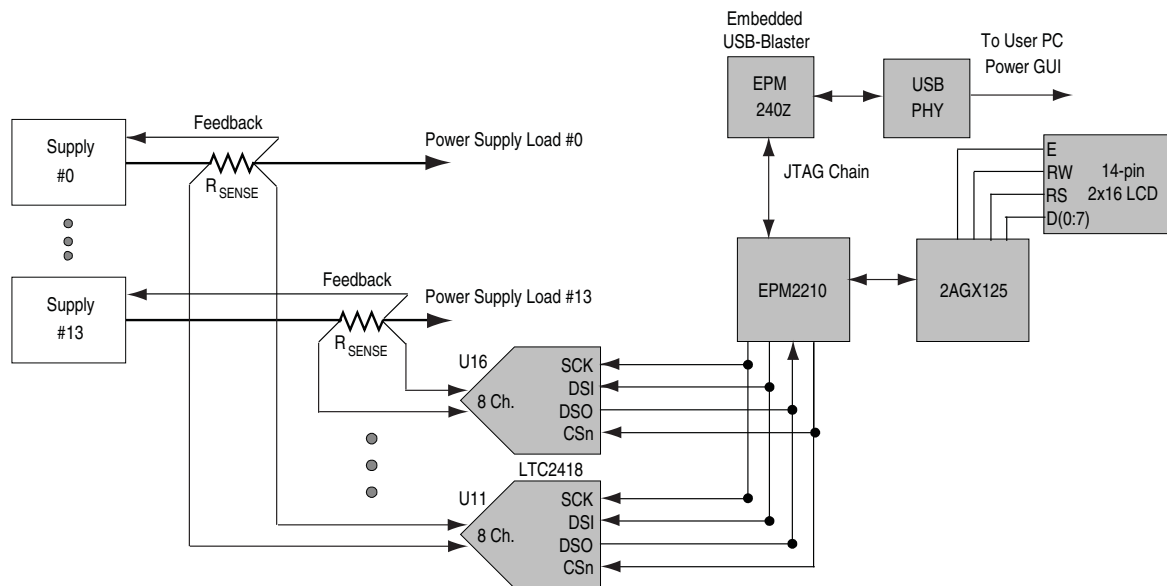


Table 2-47 lists the targeted rails. The Net Name column specifies the name of the rail being measured and the Device Pin column specifies the devices attached to the rail. If no subnet is named, the power is the total output power for that voltage.

Table 2-47. Power Rails Measurement Based on the Rotary Switch Position (Part 1 of 2)

Switch	Schematic Signal Name	Voltage (V)	Device Pin	Description
0	A2VCCIO_B3B_B5B_B6B	2.5	VCCIO_B3B	Bank 3B I/O power (HSMB)
			VCCIO_B5B	Bank 5B I/O power (HSMB)
			VCCIO_B7B	Bank 7B I/O power (HSMB)
1	A2VCCIO_B5A	2.5	VCCIO_B5A	Bank 5A I/O power (FSM, flash)
2	A2VCCIO_B6A	2.5	VCCIO_B6A	Bank 6A I/O power (SSRAM, MAX II, user I/O)
3	A2VCCIO_B7B_B8A	2.5	VCCIO_B7B	Bank 7B I/O power (HSMA)
			VCCIO_B8A	Bank 8A I/O power (HSMA)
4	A2VCCPD	2.5	VCCPD	I/O pre-drivers and input buffers
5	A2VCCIO_B3A_B4	1.8	VCCIO_B3A	Bank 3A I/O power (DDR2 SODIMM)
			VCCIO_B4	Bank 4 I/O power (DDR2 SODIMM)
6	A2VCCIO_B7A	1.5	VCCIO_B7A	Bank 7A I/O power (DDR3)
7	A2VCCCH_GXB	1.5	VCCH_GXB	XCVR output (TX) buffer

Table 2-47. Power Rails Measurement Based on the Rotary Switch Position (Part 2 of 2)

Switch	Schematic Signal Name	Voltage (V)	Device Pin	Description
8	A2VCCB	1.5	VCCB	Configuration RAM bits power
9	A2VCCL_GXB	1.1	VCCL_GXB	XCVR PMA TX, PMA RX, clocking
10	A2VCC	0.9	VCC	FPGA core and periphery power
11	A2VCCD_PLL	0.9	VCCD_PLL	PLL digital power
12	A2VCCA_PLL	2.5	VCCA_PLL	PLL analog power
13	A2VCCA	2.5	VCCA	XCVR PMA regulator

Table 2-48 lists the power measurement ADC component reference and manufacturing information.

Table 2-48. Power Measurement ADC Component Reference and Manufacturing Information

Board Reference	Description	Manufacturer	Manufacturing Part Number	Manufacturer Website
U11 and U16	8-channel differential 24-bit ADC	Linear Technology	LTC2418CGN#PBF	www.linear.com



Statement of China-RoHS Compliance

Table 2-49 lists hazardous substances included with the kit.

Table 2-49. Table of Hazardous Substances' Name and Concentration *Notes (1), (2)*

Part Name	Lead (Pb)	Cadmium (Cd)	Hexavalent Chromium (Cr6+)	Mercury (Hg)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl Ethers (PBDE)
Arria II GX development board	X*	0	0	0	0	0
12 V power supply	0	0	0	0	0	0
Type A-B USB cable	0	0	0	0	0	0
User guide	0	0	0	0	0	0

Notes to Table 2-49:

- (1) 0 indicates that the concentration of the hazardous substance in all homogeneous materials in the parts is below the relevant threshold of the SJ/T11363-2006 standard.
- (2) X* indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard, but it is exempted by EU RoHS.

Revision History

The following table displays the revision history for this reference manual.

Date and Document Version	Changes Made	Summary of Changes
July 2010 v1.0	Initial release.	—

How to Contact Altera

For the most up-to-date information about Altera products, refer to the following table.

Contact <i>(Note 1)</i>	Contact Method	Address
Technical support	Website	www.altera.com/support
Technical training	Website	www.altera.com/training
	Email	custrain@altera.com
Product literature	Website	www.altera.com/literature
Non-technical support (General) (Software Licensing)	Email	nacomp@altera.com
	Email	authorization@altera.com

Note to Table:

(1) You can also contact your local Altera sales office or sales representative.

Typographic Conventions

This document uses the typographic conventions shown in the following table.

Visual Cue	Meaning
Bold Type with Initial Capital Letters	Indicates command names, dialog box titles, dialog box options, and other GUI labels. For example, Save As dialog box.
bold type	Indicates directory names, project names, disk drive names, file names, file name extensions, and software utility names. For example, qdesigns directory, d: drive, and chiptrip.gdf file.
<i>Italic Type with Initial Capital Letters</i>	Indicates document titles. For example, <i>AN 519: Design Guidelines</i> .
<i>Italic type</i>	Indicates variables. For example, $n + 1$. Variable names are enclosed in angle brackets (< >). For example, <file name> and <project name>.pdf file.
Initial Capital Letters	Indicates keyboard keys and menu names. For example, Delete key and the Options menu.
“Subheading Title”	Quotation marks indicate references to sections in a document and titles of Quartus II Help topics. For example, “Typographic Conventions.”
Courier type	Indicates signal, port, register, bit, block, and primitive names. For example, data1, tdi, and input. Active-low signals are denoted by suffix n. For example, resetn. Indicates command line commands and anything that must be typed exactly as it appears. For example, c:\qdesigns\tutorial\chiptrip.gdf. Also indicates sections of an actual file, such as a Report File, references to parts of files (for example, the AHDL keyword SUBDESIGN), and logic function names (for example, TRI).
1., 2., 3., and a., b., c., and so on.	Numbered steps indicate a list of items when the sequence of the items is important, such as the steps listed in a procedure.
■ ■	Bullets indicate a list of items when the sequence of the items is not important.
	The hand points to information that requires special attention.
	A caution calls attention to a condition or possible situation that can damage or destroy the product or your work.
	A warning calls attention to a condition or possible situation that can cause you injury.
	The angled arrow instructs you to press Enter.
	The feet direct you to more information about a particular topic.